



Intel® GW80314 I/O Companion Chip

Datasheet

Product Features

- Companion chip for the Intel® 80200 processor based on Intel® XScale™ microarchitecture (ARM* architecture compliant—no integrated core).
- Internal non-blocking, high-speed switch fabric.
- Two PCI-X ports, which can be configured as a single two port transparent bridge or as two separate embedded PCI-X ports.
- Intel® 80200 processor interface supporting up to two processors with low latency path to the SDRAM.
- Two 10/100/1000 Mbit ethernet controllers providing descriptor based access to or from any internal port including SDRAM.
- SDR/DDR SDRAM controller with data queueing to allow the increased performance of DDR memory.
- OpenPIC based multi function interrupt controller (MPIC).
- Peripheral Bus Interface providing a generic parallel port, access to flash, and access to other types of external memory.
- Two 16550 compatible UARTS with 16-byte transmit and receive FIFOs.
- I²C* two wire interface for initial configuration or saving Vital Product Data.
- 1 MB of internal high-speed static RAM for higher speed access.

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Revision History

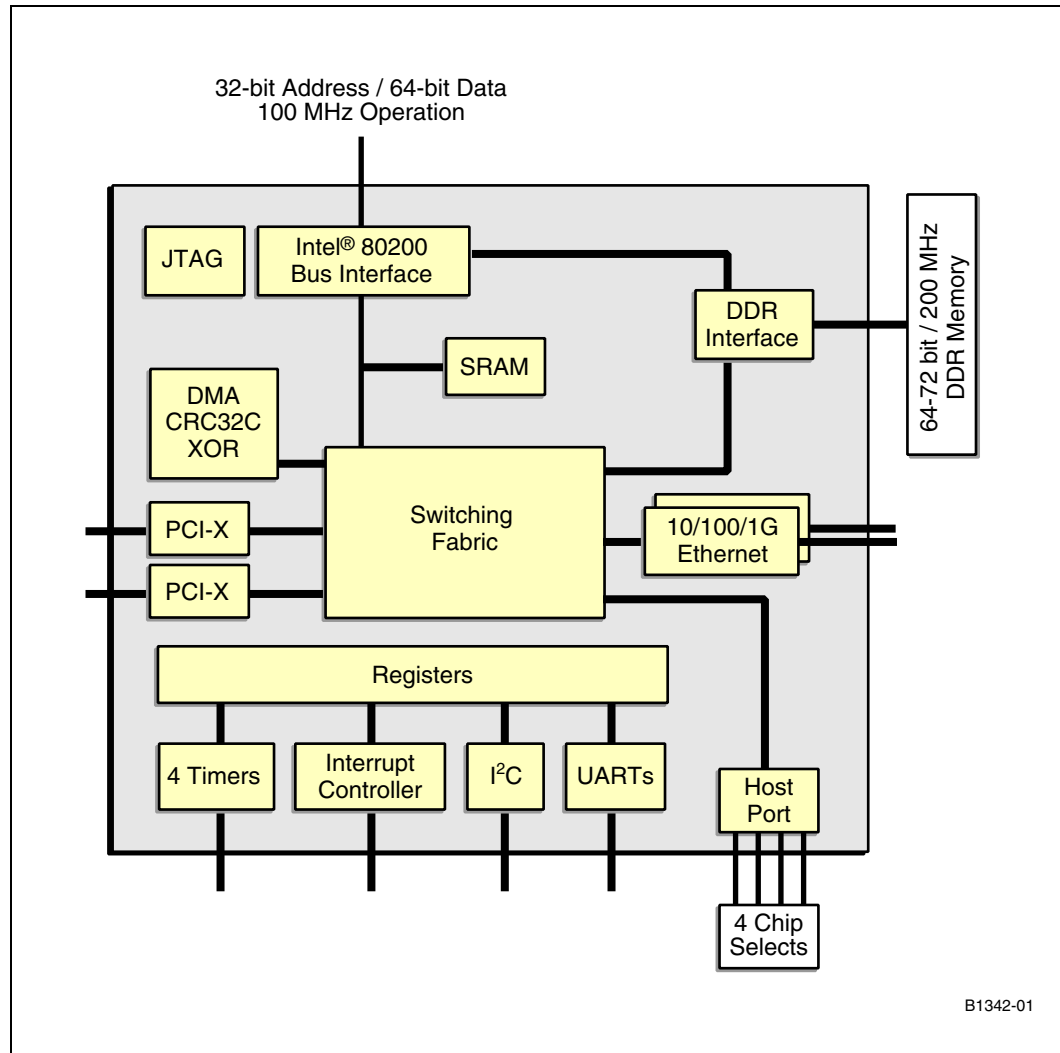
Date	Revision #	Description
September 2003	001	Initial document.

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1.0 Introduction

This is the Intel® GW80314 I/O Companion Chip (GW80314) product Target Specification (T-Spec). This document provides a functional overview, signal definitions, package definition, electrical specifications, and functional waveforms for the GW80314. Figure 1 shows a block diagram.

Figure 1. Intel® GW80314 I/O Companion Chip Block Diagram



This bridge is designed as a fabric centric, any port to any port bridge. All transactions are placed into fabric packets and routed via address based port selection to another fabric port. The bridge is based on the “store and forward” concept where transactions are buffered at the incoming port. When a packet is complete, the incoming port knows the size of the packet, and it can be burst across the fabric to the outgoing port. As the timing of the packet is deterministic at the outgoing port, the transaction can be started at the outgoing port as soon as the header arrives. All outgoing

ports have the capability to buffer incoming packets to allow for delayed access to the external bus. To limit the latency and to provide a certain quality of service, the internal packets are limited to 256 bytes in size. Larger PCI transactions are broken into 256-byte transactions at the PCI port.

1.1 Terminology

The following terms are used in this specification.

Table 1. Terms and Acronyms

Term/Acronym	Description
BAR	PCI-X Base Address Register
DMA	Direct Memory Address
Embedded	Configuration causing the PCI-X block to provide BARs and address translation mechanism to PCI-X
G/MII	Gigabit Media Independent Interface
LVTTL	Low Voltage Transistor-Transistor Logic
MAC	Media Access Controller
MIB	Management Information Base
PCI	Transfers, interfaces or logic that are <i>PCI Local Bus Specification</i> , Revision 2.3 compatible
PCI/X	Used to signify either/or PCI or PCI-X designation.
PCI-X	Transfers, interfaces or logic that may be either <i>PCI Local Bus Specification</i> , Revision 2.3 or <i>PCI-X Addendum to the PCI Local Bus Specification</i> , Revision 1.0a compatible
PHY	Physical connection device
PMA	Physical Media Attachment
PMD	Physical Media Device
Primary	A device with the PCI port attached to the processor bus side in a homogeneous, transparent system.
RMON	Remote Monitoring
RX	Receiver
Secondary	A device with the PCI port not attached to the host processor in a homogeneous, transparent system.
SNMP	Simple Network Management Protocol
STTL	Schottky Transistor-Transistor Logic
TBI	Ten Bit Interface
Transparent	Configuration causing the PCI/X block to use base and limit registers for PCI-X side addressing.
TX	Transmitter
VLAN	Virtual Local Area Network

1.2 Other Relevant Documents

Table 2. Related Documentation™

Document Title	Document# / Contact
Intel® 80312 I/O Companion Chip Developer's Manual	273410
Intel® 80312 I/O Companion Chip Specification Update	273416
Intel® 80200 Processor based on Intel® XScale™ Microarchitecture Developer's Manual	273411
Intel® 80310 I/O Processor Chipset with Intel® XScale™ Microarchitecture Design Guide	273354
Intel® 80200 Processor based on Intel® XScale™ Microarchitecture Datasheet	273414
Intel® 80200 Processor based on Intel® XScale™ Microarchitecture Specification Update	273415
PCI Local Bus Specification, Revision 2.2	PCI Special Interest Group 1-800-433-5177 http://www.pcisig.com/home
PCI-X Addendum to the PCI Local Bus Specification, Revision 1.0a	
PCI-to-PCI Bridge Architecture Specification, Revision 1.1	
PCI System Design Guide, Revision 1.0	
PCI Hot-Plug Specification, Revision 1.0	
PCI Bus Power Management Interface Specification, Revision 1.1	
OpenPIC Specification Revision 1.2	
I ² C Peripherals for Microcontrollers	Philips Semiconductor
Advanced Configuration and Power Interface Specification, Revision 1.0 (ACPI)	http://www.teleport.com/~acpi/

NOTE: Also see our product website at: <http://developer.intel.com/design/iio/>.

2.0 Features

The Intel® GW80314 I/O Companion Chip (GW80314) is an I/O companion chip for the Intel® 80200 processor (80200) with an intelligent transparent PCI-X bridge and Gigabit Ethernet access.

2.1 Switch Fabric Unit

The purpose of the Switch Fabric Network (SFN) is to provide an interconnect fabric that is useful for on-chip communications between the blocks within the GW80314.

The Switch Fabric Unit includes the following features:

- High performance interconnect fabric for communication between GW80314 blocks
- Consistent port definition that is independent of the fabric implementation
- Protocol independent of fabric pipeline depth
- Three transaction flows using four priority levels
- 64-bit local address
- 4 or 6 deep 256 byte transaction queues (mode dependent)
- Port addressing supports up to 16 SFN ports

2.2 PCI-X Interface

The PCI/X block provides an interface to the SFN (internal switch fabric). It is able to convey transactions from the internal SFN fabric to a PCI/X bus and transactions from a PCI/X bus to the internal switch fabric. The PCI/X block also has the capability to tunnel through the SFN fabric to the other PCI/X block on the fabric providing a pseudo transparent PCI to PCI bridge. This capability is available in the GW80314 as two separate PCI/X blocks are integrated.

The PCI-X block provides the following functions:

- 64-bit capable PCI/X interface
- Secondary PCI arbiter
- CompactPCI Hot Swap controller
- Control and status registers

2.3 CIU Interface

The Intel® 80200 processor (80200) bus Core Interface Unit (CIU) provides a bridge between the 80200 bus and the Switch Fabric, an SDRAM controller, and 1 MB of on chip SRAM. It has a queuing mechanism to store requests from up to two 80200s. The requests from a given 80200 are completed on the 80200 bus in the order in which they are received. The CIU has the following features:

- Up to two 80200 on the processor bus.
- Up to four read or write requests from each processor.
- Strict ordering rules for each processor.
- Optional ECC for Processor Bus Data.
- Up to four base address registers for the switch fabric.
- Configurable software reset for the CIU and Intel 80200 processors on startup
- Configurable with and without 1 Mbyte Embedded SRAM
- Reset output for Intel 80200 processors
- One base address register for the 1 MB on-chip SRAM.
- Switch fabric access to SRAM.
- 64-bit aligned data words.
- 32-bit address decode.
- Intel 80200 External bus ECC protection
- Two-cycle wait states for write transactions to the SRAM from the processor bus.
- Three-cycle wait states for read transactions to the SRAM from the processor bus.

The CIU does not have the following features:

- Locked transactions.
- Strict ordering rules between processors.

2.4 SDRAM Controller

The SDRAM Controller Core provides an interface to single and double data rate SDRAM. The SDRAM Controller Core has the following features

- Synchronous SDRAM interface for PC100, PC200, and PC1600.
- Two port (64-bit data, 36-bit address) concurrent access to memory
- Internal arbiter with programmable priority for each port
- One port (32-bit data, 18-bit address) access to registers
- Support up to four physical (eight logical) banks
- Supports up to 32 bank interleaving (i.e., 32 pages open simultaneously)
- Flexible row and column address
- Optional ECC (single-bit error correction, multi-bit error detection)
- I/O interface compatible with DDR SDRAM
- I²C master only interface for DIMM detection
- Digital DLL for automatic DQS timing recovery

2.5 DMA/XOR Engine

The DMA/XOR engine has four identical channels operating independently. Each channel can function as a DMA engine or as an XOR engine. As a DMA engine, it can transfer data from any port to any port and provide CRC calculation on the transferred data. As an XOR engine, it can perform XOR operations on multiple blocks of data, memory fill operation, and parity checking operation. For the DMA data transfer and XOR operation, a channel can be configured to operate in Direct Mode (single operation) or Linked-List mode (multiple operations by stepping through a linked series of Command Packets in external memory).

This DMA/XOR engine supports unaligned data transfers. The alignment or unalignment of data is the responsibility of the DMA/XOR engine. The DMA/XOR registers specify the source, destination, command packet address, mode of operation, the type of mapping to achieve the proper byte alignment, and the byte count for a transaction. Note that the maximum byte count is 16 Mbytes. All DMA operations are assumed to be to prefetchable memory.

The DMA/XOR Engine has the following features:

- Four channel support. Each channel operates independently.
- Data transfer to and from any port as a DMA engine.
- XOR operation, memory fill, and parity checking as an XOR engine.
- Scatter gather (or Linked-List) and direct modes.
- XOR operation of up to 16 blocks of data.
- Directly fill the store queue with the first block of XOR data (optional)
- Interrupt on completed segment, chain, and error.
- Mode selectable byte alignment on transferred data.
- Calculate CRC on the DMA transferred data based on the CRC-32C algorithm required by the *iSCSI Specification*.
- Pipeline read requests or read and write requests for better performance.
- Go/stop/halt control of data transfer operation.

2.6 Gigabit Ethernet (GigE) Interface

The Ethernet block is made up of four major sub-blocks. It includes two Gigabit Ethernet interfaces, E0 and E1. There is a single management interface to manage the two PHY devices. Each Ethernet interface has its own statistics monitor that tracks and reports key interface statistics. Each ethernet interface supports a 256-entry hash table for address filtering. Each Ethernet interface is bridged to the SFN interface domain through a 2K byte transmit FIFO and a 4K byte Receive FIFO. There are four independent DMA engines to support transmit and receive data flows for both Ethernet interfaces. The DMA engines rely on descriptors set up in memory, the memory map of the device, and are accessed through the SFN interface. The DMA arbiter handles arbitration for the SFN interface. A register bus interface is provided for the register access and status monitor control.

The GigE interface has the following features:

- Full support for 10/100/1000Mbps/s Ethernet standards IEEE 802.3, 802.3u, 802.3x, 802.3z, 802.3ac.
- Full/Half-duplex support at 10/100Mbps/s, full-duplex only Gigabit Ethernet support.
- MAC Control Sublayer w/PAUSE, Extended OPCODE Support.
- MII Management w/suppressed preamble, sequential cycle, variable clock features.
- 8-bit MAC engine optimized for size, reduced latency.
- Optional Half-Duplex back-pressure (10/100Mbps/s only).
- Hash table support for packet filtering.
- VLAN packet filtering support.
- Standard register Read/Write interface.
- 2K/4K transmit/receive FIFOs for data flow synchronization.
- Two independent DMA channels per Ethernet port, one transmit and one receive.
- Four transmit priority descriptor queues controlled via transmit priority tagging.
- Four receive priority descriptor queues controlled by receive packet filtering priority.
- Collisions detect and retransmit error handling.
- PHY management interface.
- Statistics monitoring and logging. Support for RMON MIB group 1, RMON MIB group 2 if table counters, RMON MIB group3, RMON MIB group 9, RMON MIB 2, and the dot 3 Ethernet MIB.

2.7 Interrupt Controller

The interrupt controller is a programmable, register based, and multiple port design that meets *OpenPIC Specification*, Revision 1.2.

The interrupt controller has the following features:

- Support for two Intel 80200 Processors
- Sixteen interrupt priority levels (0 to 15).
- Level/edge sensibility is programmable for 24 IRQ inputs.
- Level/edge sensibility is programmable for four output pins.
- Up to 24 input interrupt pins.
- Up to four output interrupt pins.
- Four doorbell registers for additional interrupts.
- Four general purpose Mailbox registers.
- Four global precision timers.
- All registers are Read/Write 32 bits based.
- Multiple Delivery modes are supported:
 - Directed-single destination
 - Directed-multicast
 - Distributed-multiple destination
- Nesting of interrupt events
- Spurious Vector Generation capable
- Soft Set Override for all input sources (maximum 24)
- Processor initialization registers.
- All registers are at “Known Reset State” on power up.

2.8 General Purpose I/O (GPIO) Block

The GPIO block contains the general purpose I/O functions available in the GW80314. They include:

- Two 16450 compatible UARTs with 16-byte incoming and 16-byte outgoing FIFOs.
- One General purpose I²C interface port used for initialization and storing of PCI VPD data.
- One 8-bit General purpose parallel I/O port (shared with UART pins).
- One configurable 8-, 16-, or 32-bit Peripheral Bus Interface for interfacing to external SRAM/ROM.

All the interfaces are configurable via the internal configuration bus.

3.0 Package Information

3.1 Package Introduction

The GW80314 is offered in a 1025-lead HSBGA (Heat Slug Ball Grid Array) thermally enhanced package. This is a perimeter array package with 904 ball connections in the outer area of the package and a square 11x11 grid of ball connections in the middle area of the package. See [Figure 2 “1025-Lead HSBGA Package Drawing”](#) on page 39.

3.1.1 Functional Signal Definitions

Signals are classified according to the types defined in [Table 3](#).

Table 3. Signal Type Definitions

Signal Type	Definition
I	Standard input only signal.
IO (5V)	Standard tristate input/output (5V tolerant)
I(5V)	Standard input only signal (5 V tolerant)
I(PD)	Standard input only signal with internal Pull Down.
I(PU)	Standard input only signal with internal Pull Up.
AI	Analog Input Signal
O	Standard output only signal.
OD	Open drain output that allows multiple devices to share as a wire-OR
OD(5V)	Open drain output that allows multiple devices to share as a wire-OR (5 V tolerant)
TO	Standard tristate output only signal.
IO	Standard Tristate input/output signal.
IO(OD)	Open drain input/output that allows multiple devices to share as a wire-OR when it is used as output.
IO(OD_5V)	Open drain input/output that allows multiple devices to share as a wire-OR when it is used as output. (5 V tolerant)
S	Supply Pin, either a V_{CC} or V_{SS} .

3.1.2 Intel® XScale™ Microprocessor Bus Signals

This section describes the GW80314 Intel® XScale™ microprocessor signals which are 3.3 V LVTTTL compatible.

Table 4. Intel® XScale™ Microprocessor Bus Signals

Pin Name	Count	Pin Type	Description
XS_A[15:0]	16	I	Address: During the first cycle of the issue phase, it carries the upper 16 bits of the address for the access. During the second cycle of the issues phase, it carries the lower 16 bits of the address.
XS_ABORT	1	O	Transaction Abort: Indicates the next transaction on the data bus is aborted.
XS_BE[7:0]	8	IO	Processor Bus Byte Enables.
XS_CLK	1	IO	Intel® XScale™ microprocessor bus clock: Output clock for Intel® XScale™ microprocessor interface and SDRAM controller. This pin acts as an input in Scan Mode.
XS_CWF/ DBuswidth	1	O	Critical word first: Indicates the order in which the current 32-byte read burst is returning. Also when the Intel® XScale™ microprocessor bus is in reset this signal is driven low to indicated data bus width is 64-bit.
XS_DQ[63:0]	64	IO	Data bus.
XS_DVALID[1:0]	2	O	Data Valid: One for each Intel® XScale™ microprocessor on the bus. When asserted high, it indicates that two cycles later, data is valid on XS_DQ, XS_BE, and XS_ECC.
XS_HOLD[1:0]	2	O	Signal to Intel® XScale™ microprocessor to request Intel® XScale™ microprocessor to release the Intel® XScale™ microprocessor bus.
XS_HLDA[1:0] ¹	2	I	Signal from Intel® XScale™ microprocessor to acknowledge the release of the Intel® XScale™ microprocessor bus in response to the assertion of the corresponding XS_HOLD signal.
XS_ECC[7:0]	8	IO	Data Check Bits for Intel® XScale™ microprocessor ECC Bus Protect.
XS_FIQ[1]/PWRUP_SD_ BYP (Configuration Pin)	1	IO	Interrupt: indicates a fast interrupt to processor 1. During powerup this pin is latched at the rising edge of reset and used to enable the SDRAM PLL bypass mode when latched high.
XS_FIQ[0]	1	O	Interrupt: indicates a fast interrupt to processor 0.
XS_IRQ[1]/ PWRUP_XS_BYP (Configuration Pin)	1	IO	Interrupt: indicates a interrupt to processor 1. During powerup this pin is latched at the rising edge of reset and is used to enable the Intel® XScale™ microprocessor PLL bypass mode when latched high.
XS_IRQ[0]/ PWRUP_FADJ Configuration Pin	1	IO	Interrupt: indicates a interrupt to processor 0. During powerup this pin is used to program Intel® XScale™ microprocessor PLL frequency adjust logic. • PWRUP_FADJ = 0, XScale PLL Frequency = 3/4 * SFN_CLK. • PWRUP_FADJ = 1, XScale PLL Frequency = SFN_CLK.
XS_LEN[2:0]	3	I	Control and length access: During the first cycle of the issue phase: • XS_LEN[2] (ADS#) the start of a bus request. • XS_LEN[0] (W/R#) indicates whether the current request is a read (XS_LEN[0] = 0) or a write (XS_LEN[0] = 1). During the second cycle of the issue phase: • XS_LEN[2:0] indicates the length of the request.
XS_RESET#	1	O	Reset pin: When output is low the Intel® XScale™ microprocessor bus is reset and Intel® XScale™ microprocessor interface is in reset.
Intel® XScale™ microprocessor Pin Count	113		

NOTES:

1. For single processor configuration, XS_HLDA[0] should be tied low and XS_HLDA[1] should be tied high.

3.1.3 SDRAM Controller Signals

This section describes signals for the GW80314 SDRAM controller. Signals in this group are SSTL compatible.

Table 5. SDRAM Signals

Pin Name	Count	Pin Type	Description
SD_A[13:0]	14	TO	Address: Address and command bus
SD_BA[1:0]	2	TO	Bank Address: Indicates to which bank an Active, Read, Write, or Precharge command is being applied.
SD_CAS#	1	TO	Column Address Strobe: SD_CAS#, SD_RAS#, and SD_WE# identify the command being sent to the DRAM devices.
SD_CLK[3:0]	4	TO	Clock Out: Clock outputs for SDRAM DIMMs. All address and control signals are valid on the positive edge of SD_CLK.
SD_CLK#[3:0]	4	TO	Clock Out Inverted: Clock outputs for SDRAM DIMMs
SD_CLKEN	1	TO	Clock Enable
SD_CKFB I	1	I	DDR SDRAM system flight time removal feedback input.
SD_CKFB O	1	O	DDR SDRAM system flight time removal feedback output.
SD_CS#[7:0]	8	TO	Chip Select: Enable indicating the command on SD_CAS#, SD_RAS#, and SD_WE# is valid.
SD_DQ[63:0]	64	IO	Data Bus: Output with write to RAM, and input with read from RAM.
SD_DQS/DM[17:9]	9	IO	High Data Strobe/Data Mask: Output with write to RAM, and input with read from RAM. Edge-aligned with read data, and center-aligned with write data. Used as Data Mask bits in 8-bit/16-bit wide RAM DDR systems that require only 9 strobes.
SD_DQS[8]	1	IO	Low ECC Data Strobe: Output with write to RAM, and input with read from RAM. Edge-aligned with read data, and center-aligned with write data.
SD_DQS[7:0]	8	IO	Low Data Strobe: Output with write to RAM, and input with read from RAM. Edge-aligned with read data, and center-aligned with write data.
SD_ECC[7:0]	8	IO	ECC: Indicates which bytes on a write are to be updated or the error detection and correction bits.
SD_I2C_CLK	1	OD	Serial Clock: EEPROM Serial clock for serial DIMM recognition. Internally Pulled High.
SD_I2C_SDA	1	IO(OD)	Serial Data: EEPROM Serial data line serial DIMM recognition. During powerup this pin is used to enable the SDRAM PLL bypass mode. Internally Pulled High.
SD_RAS#	1	TO	Row Address Strobe: SD_CAS#, SD_RAS#, and SD_WE# identify the command being sent to the DRAM devices.
SD_VREF	1	AI	Input threshold reference for the interface used on the DDR interface.
SD_WE#	1	TO	Write Enable: SD_CAS#, SD_RAS#, and SD_WE# identify the command being sent to the DRAM devices.
SD_PWRDELAY	1	I	Indicates healthy power supply. When high during chip reset, the memory controller will execute a power failure sequence.
DDR Pin Count	132		

3.1.4 Dual-Gigabit Ethernet (GigE) Interface Signals

This section describes signals for the GW80314 dual-ethernet controller. Signals in this group are 3.3 V LVTTTL compatible.

Table 6. GigE Signals (Sheet 1 of 3)

Pin Name	Count	Pin Type	Description
Port 0			
E0_TCG[3:0]	4	TO	All modes: Transmit Code Group Lower Nibble.
E0_TCG[7:4]	4	TO	G/MII mode: Transmit Code Group Upper Nibble. TBI mode: Transmit Code Group Upper Nibble.
E0_TCG[8]	1	TO	MII mode: Transmit Enable. This signal is synchronous to E0_TX_CLK and provides precise framing for data carried on E0_TCG[3:0] for the external PMA. It is asserted when E0_TCG[3:0] contains valid data to be transmitted. G/MII mode: Transmit Enable. This signal is synchronous to GTX_CLK and provides precise framing for data carried on E0_TCG[7:0] for the external PMA. It is asserted when E0_TCG[7:0] contains valid data to be transmitted. TBI mode: Transmit Code Group bit 8. Synchronous to GTX_CLK.
E0_TCG[9]	1	TO	MII mode: Transmit Error. This signal is synchronous to E0_TX_CLK and provides error indications. G/MII mode: Transmit Error. This signal is synchronous to GTX_CLK and provides error indications. TBI mode: Transmit Code Group bit 9. Synchronous to GTX_CLK.
E0_RCG[3:0]	4	I	All modes: Receive Code Group Lower Nibble. This is a group of four signals, sourced from an external PMA, that contains data aligned on nibble boundaries and are driven synchronous to the E0_CLK. E0_RCG[3] is the most significant bit and E0_RCG[0] is the least significant bit.
E0_RCG[7:4]	4	I	G/MII mode: Receive Code Group Upper Nibble This is a group of four signals, sourced from an external PMA, that contains data aligned on byte boundaries and are driven synchronous to the E0_CLK. E0_RCG[7] is most significant bit. TBI mode: Receive Code Group Upper Nibble.
E0_RCG[8]	1	I	G/MII modes: Receive Data Valid. This indicates that the external PMA is presenting recovered and decoded nibbles on the E0_RCG signals, and that E0_CLK is synchronous to the recovered data in 100 Mb/s and 1000 Mb/s operation. This signal will encompass the frame, starting with the Start-of-Frame delimiter (JK) and excluding any End-of-Frame delimiter (TR). TBI Mode: Transmit Code Group bit 8.
E0_RCG[9]	1	I	G/MII modes: Receive Error. This signal is synchronous to E0_CLK/E0_PMA_CLK0 and provides media error indications. TBI mode: Transmit Code Group bit 9.
E0_PCRS_SDET	1	I	G/MII modes: PHY Carrier Sense indication. TBI mode: Indicates signals detected.
E0_PCOL_RBCM	1	IO	G/MII modes: PHY Collision Input. TBI mode: Receive Byte Clock mode output. When low the E0_PMA_CLK0 and E0_PMA_CLK1 are active as half rate clocks. When high the E0_PMA_CLK0 is active as a 125MHz clock input.
E0_ECMDT	1	TO	TBI mode: Enable Comma Detect. Enables SERDES to perform code group alignment upon detection of comma.
E0_EWRAP	1	TO	TBI mode: Enable Wrap. Enables SERDES to loop transmit signals to receive (Loopback).
E0_PRBSEN	1	TO	TBI mode: PRBS Enable. Used to enable PRBS test mode inside TBI SERDES devices.
E0_PRBS_PASS	1	I	TBI mode: PRBS Pass indicator input (high = pass).
E0_RXCLK/ E0_PMA_CLK0	1	I	G/MII modes: Receive Clock from PMA. TBI mode: PMA Receive Clk 0 or 125 MHz Receive Clock depending on state of RBCMODE.

Table 6. GigE Signals (Sheet 2 of 3)

Pin Name	Count	Pin Type	Description
E0_TXCLK/ E0_PMA_CLK1	1	I	G/MII mode: 2.5Mhz or 25MHz Transmit Clock. TBI mode: PMA Receive Clk 1.
Port 1			
E1_TCG[3:0]	4	TO	All modes: Transmit Code Group Lower Nibble.
E1_TCG[7:4]	4	TO	G/MII mode: Transmit Code Group Upper Nibble. TBI mode: Transmit Code Group Upper Nibble.
E1_TCG[8]	1	TO	MII mode: Transmit Enable. This signal is synchronous to E1_TX_CLK and provides precise framing for data carried on E1_TCG[3:0] for the external PMA. It is asserted when E1_TCG[3:0] contains valid data to be transmitted. G/MII mode: Transmit Enable. This signal is synchronous to GTX_CLK and provides precise framing for data carried on E1_TCG[7:0] for the external PMA. It is asserted when E1_TCG[7:0] contains valid data to be transmitted. TBI mode: Transmit Code Group bit 8. Synchronous to GTX_CLK.
E1_TCG[9]	1	TO	MII mode: Transmit Error. This signal is synchronous to E1_TX_CLK and provides error indications. G/MII mode: Transmit Error. This signal is synchronous to GTX_CLK and provides error indications. TBI mode: Transmit Code Group bit 9. Synchronous to GTX_CLK.
E1_RCG[3:0]	4	I	All modes: Receive Code Group Lower Nibble. This is a group of 4 signals, sourced from an external PMA, that contains data aligned on nibble boundaries and are driven synchronous to the E1_CLK. E1_RCG[3] is the most significant bit and E1_RCG[0] is the least significant bit.
E1_RCG[7:4]	4	I	G/MII mode: Receive Code Group Upper Nibble This is a group of 4 signals, sourced from an external PMA, that contains data aligned on byte boundaries and are driven synchronous to the E1_CLK. E1_RCG[7] is most significant bit. TBI mode: Receive Code Group Upper Nibble.
E1_RCG[8]	1	I	G/MII modes: Receive Data Valid. This indicates that the external PMA is presenting recovered and decoded nibbles on the E1_RCG signals, and that E1_CLK is synchronous to the recovered data in 100 Mb/s and 1000 Mb/s operation. This signal will encompass the frame, starting with the Start-of-Frame delimiter (JK) and excluding any End-of-Frame delimiter (TR). TBI Mode: Transmit Code Group bit 8.
E1_RCG[9]	1	I	G/MII modes: Receive Error. This signal is synchronous to E1_CLK/E1_PMA_CLK0 and provides media error indications. TBI mode: Transmit Code Group bit 9.
E1_PCRS_SDET	1	I	G/MII modes: PHY Carrier Sense indication. TBI mode: Indicates signals detected.
E1_PCOL_RBCM	1	IO	G/MII modes: PHY Collision Input. TBI mode: Receive Byte Clock mode output. When low the E1_PMA_CLK0 and E1_PMA_CLK1 are active as half rate clocks. When high the E1_PMA_CLK0 is active as a 125 MHz clock input.
E1_ECMDT	1	TO	TBI mode: Enable Comma Detect. Enables SERDES to perform code group alignment upon detection of comma.
E1_EWRAP	1	TO	TBI mode: Enable Wrap. Enables SERDES to loop transmit signals to receive (Loopback).
E1_PRBSEN	1	TO	TBI mode: PRBS Enable. Used to enable PRBS test mode inside TBI SERDES devices.
E1_PRBS_PASS	1	I	TBI mode: PRBS Pass indicator input (high = pass).
E1_RXCLK/ E1_PMA_CLK0	1	I	G/MII modes: Receive Clock from PMA. TBI mode: PMA Receive Clk 0 or 125 MHz Receive Clock depending on state of RBCMODE.

Table 6. GigE Signals (Sheet 3 of 3)

Pin Name	Count	Pin Type	Description
E1_TXCLK/ E1_PMA_CLK1	1	I	G/MII mode: 2.5 MHz or 25 MHz Transmit Clock. TBI mode: PMA Receive Clk 1.
Management interface			
MDC	1	O	Management Data Clock (2.5 MHz by 802.3 Specification.)
MDIO	1	IO	Management Data I/O Bidirectional Pin.
Gigabit Clocks			
REF125M	1	I	All Modes: 125 MHz reference clock input.
GTX_CLK	1	O	All Modes: 125 MHz transmit clock output.
GigE Pin Count	60		

3.1.5 Peripheral Bus Interface Signals

This section describes signals for the GW80314 Peripheral Bus. Signals in this group are 3.3 V LVTTTL compatible.

Table 7. Peripheral Bus Interface Signals

Pin Name	Count	Pin Type	Description
PBI_AD[31:0]	32	IO	Address/Data Bus.
PBI_OE#	1	O	Output Enable.
PBI_CS#[3:0]	4	O	Chip Selects: Active low signal indicating that an external device has been selected for access.
PBI_LE	1	O	Latch Enable: Address latch signal to indicate when addresses are valid on the PBI_AD bus.
PBI_RDY#	1	I	Ready Input: In handshake mode, indicates that external device is ready to commence transfer.
PBI_RW	1	O	Read/Write Enable: Low indicates a write access is underway.
PBI Pin Count	40		

3.1.6 P1 PCI/X Signals

This section describes the GW80314 PCI/X signals on the P1 PCI/X bus.

Table 8. P1 PCI/X Signals (Sheet 1 of 2)

Pin Name	Count	Pin Type	Description
P1_ACK64#	1	IO(5V)	Acknowledge 64-bit transaction: Active low signal asserted by a target to indicate its willingness to participate in a 64-bit transaction. Driven by the target; sampled by the master. Rescinded by the target at the end of the transaction.
P1_AD[63:0]	64	IO(5V)	Address/Data Bus: Address and data are multiplexed over these pins providing a 64-bit address/data bus.
P1_CBE#[7:0]	8	IO(5V)	Bus Command and Byte Enable Lines: Command and byte enable information is multiplexed over all eight CBE lines.
P1_CLK_IN	1	I(5V)	PCI Input Clock: Clock In for the PCI/X Port 1 interface used to generate fixed timing parameters. P1_CLK_IN can operate between 25 and 133 MHz
P1_CLK_OUT	1	O(5V)	PCI Output Clock: Clock out for the PCI/X Port 1 interface. This is a valid clock output only when this interface is used as the controlling resource.
P1_DEVSEL#	1	IO(5V)	Device Select: An active low indication from an agent that is the target of the current transaction. Driven by the target; sampled by the master. Rescinded by the target at the end of the transaction.
P1_FRAME#	1	IO(5V)	Cycle Frame for PCI/X Bus: An active low indication from the current bus master of the beginning and end of a transaction. Driven by the bus master; sampled by the selected target. Rescinded by the bus master at the end of the transaction.
P1_GNT#[1]	1	IO(5V)	Grant: This is an input when an external arbiter is used and an output when the internal arbiter is used. As an input it is used by the external arbiter to grant the bus to the GW80314. As an output it is used by the internal arbiter to grant the bus to an external master.
P1_GNT#[7:2]	6	TO	Grant: These are used by the internal arbiter to grant the bus to an external master
P1_IDSEL	1	I(5V)	Initialization Device Select: Used as a chip select during Configuration 0 read and write transactions
P1_INTA#	1	IO(OD_5V)	Interrupt A: An active low level sensitive indication of an interrupt.
P1_INTB#	1	IO(OD_5V)	Interrupt B: An active low level sensitive indication of an interrupt.
P1_INTC#	1	IO(OD_5V)	Interrupt C: An active low level sensitive indication of an interrupt.
P1_INTD#	1	IO(OD_5V)	Interrupt B: An active low level sensitive indication of an interrupt.
P1_IRDY#	1	IO(5V)	Initiator Ready: An active low indication of the current bus master's ability to complete the current data phase. Driven by the master; sampled by the selected target.
P1_M66EN	1	I(5V)	PCI 66 MHz Enable: Controls the 33/66 MHz clock generation when in PCI mode. When pulled low, it configures the PCI Port 1 PLL clock output for 33 MHz. When pulled high, it configures the PCI Port 1 PLL for 66 MHz operation.
P1_PAR	1	IO(5V)	Parity: Carries even parity across P1_AD[31:0] and P1_C/BE[3:0]. Driven by the master for the address and write data phases. Driven by the target for read data phases.
P1_PAR64	1	IO(5V)	Parity upper dword: Carries even parity across P1_AD[63:32] and P1_CBE[7:4]. Driven by the master for address and write data phases. Driven by the target for read data phases.
P1_PCIXCAP[1:0]	2	I(5V)	PCI/X Capability pin: Indicates the speed and mode of PCI/X interface when configured as the control resource (P1_RSTDIR = 1).
P1_PERR#	1	IO(5V)	Parity Error: An active low indication of a data parity error. Driven by the target receiving data. Rescinded by that agent at the end of the transaction.

Table 8. P1 PCI/X Signals (Sheet 2 of 2)

Pin Name	Count	Pin Type	Description
P1_PME#	1	IO(5V)	Power Management (optional interrupt pin)
P1_REQ#[1]	1	IO(5V)	Bus Request: This is an output when an external arbiter is used and an input when the internal arbiter is used. As an input it is used by an external master to request the bus. As an output it is used by the GW80314 to request the bus.
P1_REQ#[7:2]	6	I(5V)	Bus Request: These signals are used by external masters to request the PCI/X bus.
P1_REQ64#	1	IO(5V)	Request 64-bit transfer: An active low indication from the current master of its choice to perform 64-bit transactions. Rescinded by the bus master at the end of the transaction.
P1_RST#	1	IO(5V)	Reset: Asynchronous active low reset for PCI/X interface. If the interface is the secondary side in a transparent bridge this pin is configured as an output.
P1_RSTDIR	1	I(5V)	Reset Direction: 0 = P1_RST# is input and P1_CLK_OUT is driven to 0. 1 = P1_RST# is output and P1_CLK_OUT is generated (PCI Port 1 is controlling resource).
P1_SERR#	1	IO(OD_5V)	System Error: An active low indication of address parity error.
P1_STOP#	1	IO(5V)	Stop: An active low indication from the target of its desire to stop the current transition. Sampled by the master; rescinded by the target at the end of the transaction
P1_TRDY#	1	IO(5V)	Target Ready: An active low indication of the current target's ability to complete the data phase. Driven by the target; sampled by the current bus master. Rescinded by the target at the end of the transaction.
P1 PCI/X Pin Count	110		

3.1.7 P2 PCI/X Signals

This section describes the GW80314 PCI/X signals on P2 PCI/X bus.

Table 9. P2 PCI/X Signals (Sheet 1 of 2)

Pin Name	Count	Pin Type	Description
P2_ACK64#	1	IO(5V)	Acknowledge 64-bit transaction: Active low signal asserted by a target to indicate its willingness to participate in a 64-bit transaction. Driven by the target; sampled by the master. Rescinded by the target at the end of the transaction.
P2_AD[63:0]	64	IO(5V)	Address/Data Bus: Address and data are multiplexed over these pins providing a 64-bit address/data bus.
P2_CBE#[7:0]	8	IO(5V)	Bus Command and Byte Enable Lines: Command and byte enable information is multiplexed over all eight CBE lines.
P2_CLK_IN	1	I(5V)	PCI Input Clock: Clock input for the PCI/X Port 1 interface used to generate fixed timing parameters. P2_CLK_IN can operate between 25 and 133 MHz.
P2_CLK_OUT	1	O(5V)	PCI Output Clock: Clock out for the PCI/X Port 2 interface. This is a valid clock output only when this interface is used as the controlling resource.
P2_DEVSEL#	1	IO(5V)	Device Select: An active low indication from an agent that is the target of the current transaction. Driven by the target; sampled by the master. Rescinded by the target at the end of the transaction.
P2_FRAME#	1	IO(5V)	Cycle Frame for PCI/X Bus: An active low indication from the current bus master of the beginning and end of a transaction. Driven by the bus master; sampled by the selected target. Rescinded by the bus master at the end of the transaction.
P2_GNT#[1]	1	IO(5V)	Grant: This is an input when an external arbiter is used and an output when the internal arbiter is used. As an input it is used by the external arbiter to grant the bus to the GW80314. As an output it is used by the internal arbiter to grant the bus to an external master.
P2_GNT#[7:2]	6	TO	Grant: These are used by the internal arbiter to grant the bus to an external master.
P2_IDSEL	1	I(5V)	Initialization Device Select: Used as a chip select during Configuration read and write transactions.
P2_INTA#	1	IO(OD_5V)	Interrupt A: An active low level sensitive indication of an interrupt.
P2_INTB#	1	IO(OD_5V)	Interrupt B: An active low level sensitive indication of an interrupt.
P2_INTC#	1	IO(OD_5V)	Interrupt C: An active low level sensitive indication of an interrupt.
P2_INTD#	1	IO(OD_5V)	Interrupt D: An active low level sensitive indication of an interrupt.
P2_IRDY#	1	IO(5V)	Initiator Ready: An active low indication of the current bus master's ability to complete the current data phase. Driven by the master; sampled by the selected target.
P2_M66EN	1	I(5V)	PCI 66 MHz Enable: Controls 33/66 MHz clock generation when in PCI mode. When pulled low, it configures the PCI Port 2 PLL clock output for 33MHz operation. When pulled high, it configures the PCI Port 2 PLL clock output for 66MHz operation.
P2_PAR	1	IO(5V)	Parity: Carries even parity across P2_AD[31:0] and P2_C/BE[3:0]. Driven by the master for the address and write data phases. Driven by the target for read data phases.
P2_PAR64	1	IO(5V)	Parity upper dword: Carries even parity across P2_AD[63:32] and P2_CBE[7:4]. Driven by the master for address and write data phases. Driven by the target for read data phases.
P2_PCIXCAP[1:0]	2	I(5V)	PCI/X Capability pin: Indicates the speed and mode of PCI/X interface when configured as the control resource (P2_RSTDIR = 1).
P2_PERR#	1	IO(5V)	Parity Error: An active low indication of a data parity error. Driven by the target receiving data. Rescinded by that agent at the end of the transaction.

Table 9. P2 PCI/X Signals (Sheet 2 of 2)

Pin Name	Count	Pin Type	Description
P2_PME#	1	IO(5V)	Power Management (optional interrupt pin).
P2_REQ#[1]	1	IO(5V)	Bus Request: This is an output when an external arbiter is used and an input when the internal arbiter is used. As an input it is used by an external master to request the bus. As an output it is used by the GW80314 to request the bus.
P2_REQ#[7:2]	6	I(5V)	Bus Request: These signals are used by external masters to request the PCI/X bus.
P2_REQ64#	1	IO(5V)	Request 64-bit transfer: An active low indication from the current master of its choice to perform 64-bit transactions. Rescinded by the bus master at the end of the transaction.
P2_RST#	1	IO(5V)	Reset: Asynchronous active low reset for PCI/X interface
P2_RSTDIR	1	I(5V)	Reset Direction: 0 = P2_RST# is input and P2_CLK_OUT is driven to 0. 1 = P2_RST# is output and P2_CLK_OUT is generated (PCI Port 2 is controlling resource).
P2_SERR#	1	IO(OD_5V)	System Error: An active low indication of address parity error.
P2_STOP#	1	IO(5V)	Stop: An active low indication from the target of its desire to stop the current transition. Sampled by the master; rescinded by the target at the end of the transaction
P2_TRDY#	1	IO(5V)	Target Ready: An active low indication of the current target's ability to complete the data phase. Driven by the target; sampled by the current bus master. Rescinded by the target at the end of the transaction.
P2 PCI/X Pin Count	110		

3.1.8 P1 Hot Swap Signals

This section describes the GW80314 PCI Port 1 Hot Swap signals.

Table 10. P1 Hot Swap Signals

Pin Name	Count	Pin Type	Description
P1_ENUM#	1	OD	System Enumeration: Used to notify system host that a board has been freshly inserted or extracted from the system.
P1_ES	1	I(5V)	Ejector Switch: Indicates the status of Hot Swap board ejector switch.
P1_HEALTHY#	1	I(5V)	Board healthy - In a CPCI Hot Swap environment, indicates the board is ready to be released from reset and become an active agent on the PCI bus. Negation of P1_HEALTHY# resets all GW80314 resources, including PLLs. Additionally, all GW80314 outputs are tristated when this pin is negated; some inputs and bi-directionals are inhibited.
P1_HS_64EN#	1	I	PCI/X 64-bit Enable: An active low indication that a CompactPCI Hot Swap board is in a 64-bit slot.
P1_LED#	1	OD(5V)	LED: Controls the Hot Swap status LED.
P1 Hot Swap Pin Count	5		

3.1.9 P2 Hot Swap Signals

This section describes the GW80314 PCI Port 2 Hot Swap signals.

Table 11. P2 Hot Swap Signals

Pin Name	Count	Pin Type	Description
P2_ENUM#	1	OD	System Enumeration: Used to notify system host that a board has been freshly inserted or extracted from the system.
P2_ES	1	I(5V)	Ejector Switch: Indicates the status of Hot Swap board ejector switch.
P2_HEALTHY#	1	I(5V)	Board healthy - In a CPCI Hot Swap environment, indicates the board is ready to be released from reset and become an active agent on the PCI bus. Negation of P1_HEALTHY# resets all GW80314 resources, including PLLs. Additionally, all GW80314 outputs are tristated when this pin is negated; some inputs and bi-directionals are inhibited.
P2_HS_64EN#	1	I	PCI/X 64-bit Enable: An active low indication that a CompactPCI Hot Swap board is in a 64-bit slot.
P2_LED#	1	OD(5V)	LED: Controls the Hot Swap status LED.
P2 Hot Swap Pin Count	5		

3.1.10 Interrupt Controller Signals

This section describes signals for the GW80314 interrupt controller. Signals in this group are 3.3 V LVTTTL compatible.

Table 12. Interrupt Controller Signals

Pin Name	Count	Pin Type	Description
INT[15:8]	8	IO	Inputs representing external, incoming interrupts.
INT[7:0]	8	I	Inputs representing external, incoming interrupts.
Interrupt Total	16		

3.1.11 Dual UART Signals

This section describes signals for the GW80314 dual UARTs. Signals in this group are 3.3 V LVTTTL compatible.

Table 13. UART Signals

Pin Name	Count	Pin Type	Description
Uart0			
U0_RX	1	I	Data In: Serial input data
U0_TX	1	O	Data Out: Serial output data
U0_CTS#	1	I	Clear to Send: When low, this indicates that the MODEM or data set is ready to exchange data.
U0_RTS#	1	O	Request to Send: When low, this informs the MODEM or data set that the UART is ready to exchange data.
U0_DSR#/ GPIO[0]	1	IO	Data Set Ready Output: When low, this indicates that the MODEM or data set is ready to establish the communications link with the UART. This pin is multiplexed with GPIO[0].
U0_DTR#/ GPIO[1]	1	IO	Data Terminal Ready Output: When low, this informs the MODEM or data set that the UART is ready to establish a communications link. This pin is multiplexed with GPIO[1].
U0_DCD#/ GPIO[2]	1	IO	Data Carrier Detect Output: When low, this indicates that the data carrier has been detected by the MODEM or data set. This pin is multiplexed with GPIO[2].
U0_RI#/ GPIO[3]	1	IO	Ring Indicator Output: When low, this indicates that a telephone ringing signal has been received by the MODEM or data set. This pin is multiplexed with GPIO[3].
Uart1			
U1_RX	1	I	Data In: Serial input data
U1_TX	1	O	Data Out: Serial output data
U1_CTS#	1	I	Clear to Send: When low, this indicates that the MODEM or data set is ready to exchange data.
U1_RTS#	1	O	Request to Send: When low, this informs the MODEM or data set that the UART is ready to exchange data.
U1_DSR#/ GPIO[4]	1	IO	Data Set Ready Output: When low, this indicates that the MODEM or data set is ready to establish the communications link with the UART. This pin is multiplexed with GPIO[4].
U1_DTR#/ GPIO[5]	1	IO	Data Terminal Ready Output: When low, this informs the MODEM or data set that the UART is ready to establish a communications link. This pin is multiplexed with GPIO[5].
U1_DCD#/ GPIO[6]	1	IO	Data Carrier Detect Output: When low, this indicates that the data carrier has been detected by the MODEM or data set. This pin is multiplexed with GPIO[6].
U1_RI#/ GPIO[7]	1	IO	Ring Indicator Output: When low, this indicates that a telephone ringing signal has been received by the MODEM or data set. This pin is multiplexed with GPIO[7].
UART Pin Count	16		

3.1.12 I²C Signals

This section describes the GW80314 I²C signals, which are 3.3 V LVTTL compatible.

Table 14. I²C Signals

Pin Name	Count	Pin Type	Description
I2C_SCLK	1	OD	I ² C Serial Clock Output - EEPROM Serial clock. Internally Pulled High.
I2C_SDA	1	IO(OD)	Serial data - EEPROM Serial data line. This signal is internally Pulled High.
I2C Pin Count	2		

3.1.13 Miscellaneous Signals

This section describes the GW80314 miscellaneous signals which are 3.3 V LVTTL compatible.

Table 15. Miscellaneous Signals

Pin Name	Count	Pin Type	Description
PWRUP_PBI_BSWP (Configuration Pin)	1	I	Used during power up to determine if PBI interface is operating in Intel® XScale™ microprocessor Byte Swap Mode (1 - Enable Byte Swap Mode).
PWRUP_P1_ARB (Configuration Pin)	1	I	Used during power up to determine if the PCI1 interface uses the internal GW80314 PCI1 Arbiter (1 - Internal Arbiter Selected).
PWRUP_P1_PRIM (Configuration Pin)	1	I	Transparent Mode: Used during power up to determine if the PCI1 interface is the primary PCI/X side of the bridge (1 - PCI1 is Primary). Also used in conjunction with P1_RSTDIR to determine the source of chip reset. Embedded Mode: Used in conjunction with P1_RSTDIR to determine the source of chip reset.
PWRUP_P2_ARB (Configuration Pin)	1	I	Used during power up to determine if the PCI2 interface uses the internal GW80314 PCI2 Arbiter (1 - Internal Arbiter Selected).
PWRUP_P2_PRIM (Configuration Pin)	1	I	Transparent Mode: Used during power up to determine if the PCI2 interface is the primary PCI/X side of the bridge (1 - PCI2 is Primary). Also used in conjunction with P2_RSTDIR to determine the source of chip reset. Embedded Mode: Used in conjunction with P2_RSTDIR to determine the source of chip reset.
PWRUP_TRANS (Configuration Pin)	1	I	Used during power up to determine if P2P bridge is operating in embedded or transparent mode. 0 = Embedded Mode Operation. 1 = Transparent Mode Operation.
PWRUP_XS_SWRST (Configuration Pin)	1	I	Controls state of Software Reset inside Intel® XScale™ microprocessor CIU block (1 - XScale interface held in reset until cleared by processor).
PWRUP_P1_SWRST (Configuration Pin)	1	I	Controls state of Software Reset inside P1 PCI/X block (1 - PCI1 interface held in reset until cleared by processor).
PWRUP_P2_SWRST (Configuration Pin)	1	I	Controls state of Software Reset inside P2 PCI/X block (1 - PCI2 interface held in reset until cleared by processor).
PWRUP_P1_BYP (Configuration Pin)	1	I	Used during power up to enable P1PCI PLL bypass mode (1 - PCI1 PLL is bypassed).
PWRUP_P2_BYP (Configuration Pin)	1	I	Used during power up to enable P2 PCI PLL bypass mode (1 - PCI2 PLL is bypassed).
SFN_CLK	1	I	Fabric Clock input.
SFN_RST#	1	I	Fabric Gasket Reset and General Chip Reset.
NC_(Location)	5		No Connect Pins (NC_J35, NC_K34, NC_L6, NC_M33, NC_N6)
Misc. Pin Count	18		

3.1.14 Test Signals

This section describes the GW80314 signals used to support silicon or board-level testing. Signals in this section are 3.3 V LVTTL compatible.

Table 16. Test Signals

Pin Name	Count	Pin Type	Description
TCK	1	I	Test Clock (JTAG): Used to clock state information and data into and out of the device during boundary scan
TMS	1	I(PU)	Test Mode Select (JTAG): Used to control the state of the TAP controller. Internally Pulled High.
TDI	1	I(PU)	Test Data Input (JTAG): Used to shift data and instruction into boundary scan. Internally Pulled High.
TDO	1	TO	Test Data Output (JTAG): Used to shift data and instruction out of boundary scan
TRST#	1	I(PU)	Test Reset (JTAG): Asynchronous reset for the JTAG controller. This pin must be asserted low during the power-up reset sequence to ensure that the Boundary Scan Register elements are configured for normal system operation. Customers must assert TRST# concurrently with SF_RST or P1_RST or P2_RST (depending on powerup configurations) as part of the power-up reset sequence. Internally Pulled High. Pull-down resistor if JTAG is not used.
Test Pin Count	5		

3.1.15 PLL Power Signals

This section describes the GW80314 signals used to support on board PLLs for the various interfaces. Each AVCC pin supplies 3.3 V (typical) to each interface.

Table 17. PLL Power Signals

Pin Name	Count	Pin Type	Description
XS_PLL_AVCC (V _{CC33})	1	S	Analog Power pin for Intel® XScale™ microprocessor Interface PLL.
XS_PLL_AVSS	1	S	Analog Ground pin for Intel® XScale™ microprocessor Interface PLL.
SD_PLL_AVCC (V _{CC33})	1	S	Analog Power pin for DDR SDRAM Interface PLL.
SD_PLL_AVSS	1	S	Analog Ground pin for DDR SDRAM Interface PLL.
P1_PLL_AVCC (V _{CC33})	1	S	Analog Power pin for PCI1 Interface PLL.
P1_PLL_AVSS	1	S	Analog Ground pin for PCI1 Interface PLL.
P2_PLL_AVCC (V _{CC33})	1	S	Analog Power pin for PCI2 Interface PLL.
P2_PLL_AVSS	1	S	Analog Ground pin for PCI2 Interface PLL.
PLL Supply Count	8		

3.1.16 Power Supplies

This section describes the GW80314 power supplies used to support both I/O interfaces and Core elements.

Table 18. Power Supplies

Pin Name	Pin Type / Count	Description
VCC_CORE (V _{CC12})	S / 75	Core Power Supply for the GW80314.
VCC_PC (V _{CC33})	S / 56	I/O Power Supply for PCI Interface.
VCC_SD (V _{CC25})	S / 26	I/O Power Supply for DDR SDRAM Interface.
VCC_XS (V _{CC33})	S / 28	I/O Power Supply for Intel® XScale™ microprocessor Interface.
VSS_CORE	S / 73	Core Ground Supply for the GW80314.
VSS_IO	S / 119	I/O Ground Supply.
VCC Pin Count Total	185	
VSS Pin Count Total	192	

3.1.17 Signal Pin Mode Behavior

This section describes the GW80314 signal pin mode behavior during reset, normal operation, 32-bit PCI mode, and error correction mode.

Table 19. Signal Pin Mode Behavior (Sheet 1 of 5)

Pin Name	Reset	Norm	Hold	32-Bit PCI	32-Bit Mem	ECC Off
XS_A[15:0]	VI	VI	-	-	-	-
XS_ABORT	0	VO	-	-	-	-
XS_BE[7:0]	0	VB	-	-	-	-
XS_CLK	0	VB	-	-	-	-
XS_CWF / DBuswidth	0	VO	-	-	-	-
XS_DQ[63:0]	0	VB	-	-	-	-
XS_DVALID[1:0]	0	VO	-	-	-	-
XS_HOLD[1:0]	0	VO	-	-	-	-
XS_HLDA[1:0]	VI	VI	-	-	-	-
XS_ECC[7:0]	0	VB	-	-	-	-
XS_FIQ[1] / PWRUP_SD_BYP	L	VO	1	-	-	-
XS_FIQ[0]	0	VO	-	-	-	-
XS_IRQ[1]/PWRUP_XS_BYP	L	VO	1	-	-	-
XS_IRQ[0]/PWRUP_FADJ	L	VO	1	-	-	-
XS_LEN[2:0]	VI	VI	-	-	-	-
XS_RESET#	0	VO	-	-	-	-
SD_A[13:0]	0*	VO	-	-	-	-
SD_BA[1:0]	0*	VO	-	-	-	-
SD_CAS#	1*	VO	-	-	-	-
SD_CLK[3:0]	VO	VO	-	-	-	-
SD_CLK#[3:0]	VO	VO	-	-	-	-
SD_CLKEN	0*	VO	-	-	-	-
SD_CKFBI	VI	VI	-	-	-	-
SD_CKFBO	VO	VO	-	-	-	-
SD_CS#[7:0]	1*	VO	-	-	-	-
SD_DQ[63:32]	Z*	VB	-	-	ID	-
SD_DQ[31:0]	Z*	VB	-	-	-	-
SD_DQS[17]	Z*	VB	-	-	-	ID
SD_DQS/DM[16:9]	Z*	VB	-	-	ID	-
SD_DQS[8]	Z*	VB	-	-	-	ID
SD_DQS[7:0]	Z*	VB	-	-	-	-
SD_ECC	Z*	VB	-	-	-	ID
SD_I2C_CLK	H	VO	-	-	-	-
SD_I2C_SDA	H	VB	-	-	-	-
SD_RAS#	1*	VO	-	-	-	-
SD_WE#	1*	VO	-	-	-	-

Table 19. Signal Pin Mode Behavior (Sheet 2 of 5)

Pin Name	Reset	Norm	Hold	32-Bit PCI	32-Bit Mem	ECC Off
SD_PWRDELAY	VI	VI	-	-	-	-
E0_TCG[9:0]	VO	VO	-	-	-	-
E0_RCG[9:0]	VI	VI	-	-	-	-
E0_PCRS_SDET	VI	VI	-	-	-	-
E0_PCOL_RBCM	Z	VB	-	-	-	-
E0_ECMDT	Z	VO	-	-	-	-
E0_EWRAP	Z	VO	-	-	-	-
E0_PRBSEN	Z	VO	-	-	-	-
E0_PRBS_PASS	VI	VI	-	-	-	-
E0_RXCLK/E0_PMA_CLK0	VI	VI	-	-	-	-
E0_TXCLK/E0_PMA_CLK1	VI	VI	-	-	-	-
E1_TCG[9:0]	VO	VO	-	-	-	-
E1_RCG[9:0]	VI	VI	-	-	-	-
E1_PCRS_SDET	VI	VI	-	-	-	-
E1_PCOL_RBCM	Z	VB	-	-	-	-
E1_ECMDT	Z	VO	-	-	-	-
E1_EWRAP	Z	VO	-	-	-	-
E1_PRBSEN	Z	VO	-	-	-	-
E1_PRBS_PASS	VI	VI	-	-	-	-
E1_RXCLK/E1_PMA_CLK0	VI	VI	-	-	-	-
E1_TXCLK/E1_PMA_CLK1	VI	VI	-	-	-	-
MDC	0	VO	-	-	-	-
MDIO	Z	VB	-	-	-	-
REF125M	VI	VI	-	-	-	-
GTX_CLK	0	VO	-	-	-	-
PBI_AD[31:0]	0	VB	Z	-	-	-
PBI_OE#	1	VO	-	-	-	-
PBI_CS#[3:0]	1	VO	-	-	-	-
PBI_LE	0	VO	Z	-	-	-
PBI_RDY#	VI	VI	-	-	-	-
PBI_RW	0	VO	Z	-	-	-
P1_ACK64#	Z	VB	-	-	-	-
P1_AD[63:32]	Z	VB	-	H	-	-
P1_AD[31:0]	Z	VB	-	-	-	-
P1_CBE#[7:4]	Z	VB	-	H	-	-
P1_CBE#[3:0]	Z	VB	-	-	-	-
P1_CLK_IN	VI	VI	-	-	-	-
P1_CLK_OUT	0	VO	-	-	-	-
P1_DEVSEL#	Z	VB	-	-	-	-
P1_FRAME#	Z	VB	-	-	-	-

Table 19. Signal Pin Mode Behavior (Sheet 3 of 5)

Pin Name	Reset	Norm	Hold	32-Bit PCI	32-Bit Mem	ECC Off
P1_GNT#[1]	Z	VB	-	-	-	-
P1_GNT#[7:2]	Z	VO	-	-	-	-
P1_IDSEL	VI	VI	-	-	-	-
P1_INTA#	Z	VO	-	-	-	-
P1_INTB#	Z	VO	-	-	-	-
P1_INTC#	Z	VO	-	-	-	-
P1_INTD#	Z	VO	-	-	-	-
P1_IRDY#	Z	VB	-	-	-	-
P1_M66EN	VI	VI	-	-	-	-
P1_PAR	Z	VB	-	-	-	-
P1_PAR64	Z	VB	-	H	-	-
P1_PCIXCAP[1:0]	VI	VI	-	-	-	-
P1_PERR#	Z	VB	-	-	-	-
P1_PME#	Z	VB	-	-	-	-
P1_REQ#[1]	Z	VB	-	-	-	-
P1_REQ#[7:2]	VI	VI	-	-	-	-
P1_REQ64#	VO _M /VI _T	VO _M /VI _T	-	-	-	-
P1_RST#	VB	VB	-	-	-	-
P1_RSTDIR	VI	VI	-	-	-	-
P1_SERR#	Z	VB	-	-	-	-
P1_STOP#	VO _T /VI _M	VO _T /VI _M	-	-	-	-
P1_TRDY#	VO _T /VI _M	VO _T /VI _M	-	-	-	-
P2_ACK64#	Z	VB	-	-	-	-
P2_AD[63:32]	Z	VB	-	H	-	-
P2_AD[31:0]	Z	VB	-	-	-	-
P2_CBE#[7:4]	Z	VB	-	H	-	-
P2_CBE#[3:0]	Z	VB	-	-	-	-
P2_CLK_IN	VI	VI	-	-	-	-
P2_CLK_OUT	0	VO	-	-	-	-
P2_DEVSEL#	Z	VB	-	-	-	-
P2_FRAME#	Z	VB	-	-	-	-
P2_GNT#[1]	Z	VB	-	-	-	-
P2_GNT#[7:2]	Z	VO	-	-	-	-
P2_IDSEL	VI	VI	-	-	-	-
P2_INTA#	Z	VO	-	-	-	-
P2_INTB#	Z	VO	-	-	-	-
P2_INTC#	Z	VO	-	-	-	-
P2_INTD#	Z	VO	-	-	-	-
P2_IRDY#	Z	VB	-	-	-	-
P2_M66EN	VI	VI	-	-	-	-

Table 19. Signal Pin Mode Behavior (Sheet 4 of 5)

Pin Name	Reset	Norm	Hold	32-Bit PCI	32-Bit Mem	ECC Off
P2_PAR	Z	VB	-	-	-	-
P2_PAR64	Z	VB	-	H	-	-
P2_PCIXCAP[1:0]	VI	VI	-	-	-	-
P2_PERR#	Z	VB	-	-	-	-
P2_PME#	Z	VB	-	-	-	-
P2_REQ#[1]	Z	VB	-	-	-	-
P2_REQ#[7:2]	VI	VI	-	-	-	-
P2_REQ64#	VO _M /VI _T	VO _M /VI _T	-	-	-	-
P2_RST#	VB	VB	-	-	-	-
P2_RSTDIR	VI	VI	-	-	-	-
P2_SERR#	Z	VB	-	-	-	-
P2_STOP#	VO _T /VI _M	VO _T /VI _M	-	-	-	-
P2_TRDY#	VO _T /VI _M	VO _T /VI _M	-	-	-	-
P1_ENUM#	Z	VB	-	-	-	-
P1_ES	VI	VI	-	-	-	-
P1_HEALTHY#	VI	VI	-	-	-	-
P1_HS_64EN#	VI	VI	-	-	-	-
P1_LED#	Z	VO	-	-	-	-
P2_ENUM#	Z	VO	-	-	-	-
P2_ES	VI	VI	-	-	-	-
P2_HEALTHY#	VI	VI	-	-	-	-
P2_HS_64EN#	VI	VI	-	-	-	-
P2_LED#	Z	VO	-	-	-	-
INT[15:8]/TM_MON[7:0]	VI	VB	-	-	-	-
INT[7:0]	VI	VI	-	-	-	-
U0_RX	VI	VI	-	-	-	-
U0_TX	0	VO	-	-	-	-
U0_CTS#	VI	VI	-	-	-	-
U0_RTS#	1	VI	-	-	-	-
U0_DSR#/GPIO[0]	VI	VB	-	-	-	-
U0_DTR#/GPIO[1]	VI	VB	-	-	-	-
U0_DCD#/GPIO[2]	VI	VB	-	-	-	-
U0_RI#/GPIO[3]	VI	VB	-	-	-	-
U1_RX	VI	VI	-	-	-	-
U1_TX	0	VO	-	-	-	-
U1_CTS#	VI	VI	-	-	-	-
U1_RTS#	1	VI	-	-	-	-
U1_DSR#/GPIO[4]	VI	VB	-	-	-	-
U1_DTR#/GPIO[5]	VI	VB	-	-	-	-
U1_DCD#/GPIO[6]	VI	VB	-	-	-	-

Table 19. Signal Pin Mode Behavior (Sheet 5 of 5)

Pin Name	Reset	Norm	Hold	32-Bit PCI	32-Bit Mem	ECC Off
U1_RI#/GPIO[7]	VI	VB	-	-	-	-
I2C_SCLK	H	VO	-	-	-	-
I2C_SDA	H	VB	-	-	-	-
PWRUP_PBI_BSWP	VI	VI	-	-	-	-
PWRUP_P1_ARB	VI	VI	-	-	-	-
PWRUP_P1_PRIM	VI	VI	-	-	-	-
PWRUP_P2_ARB	VI	VI	-	-	-	-
PWRUP_P2_PRIM	VI	VI	-	-	-	-
PWRUP_TRANS	VI	VI	-	-	-	-
PWRUP_XS_SWRST	VI	VI	-	-	-	-
PWRUP_P1_SWRST	VI	VI	-	-	-	-
PWRUP_P2_SWRST	VI	VI	-	-	-	-
PWRUP_P1_BYP	VI	VI	-	-	-	-
PWRUP_P2_BYP	VI	VI	-	-	-	-
SF_CLK	VI	VI	-	-	-	-
SF_RST#	VI	VI	-	-	-	-
TCK	VI	VI	-	-	-	-
TMS	H	H	-	-	-	-
TDI	H	H	-	-	-	-
TDO	Z	VO	-	-	-	-
TRST#	H	H	-	-	-	-

NOTES:

1. 1 = driven to V_{CC}
2. Z = output disabled (floats)
3. 0 = driven to V_{SS}
4. VB = acts like a valid bidirectional pin
5. ID = input is disabled
6. VO = a valid output level is driven
7. VO_M = a valid output level is driven (PCI Master)
8. VO_T = a valid output level is driven (PCI Target)
9. H = pulled up to V_{CC}
10. L = pulled down to V_{SS}
11. VI = need to drive a valid input level
12. VI_M = need to drive a valid input level (PCI Master)
13. VI_T = need to drive a valid input level (PCI Target)
14. PD = pull-up disabled
15. * = after power fail sequence completes

3.1.18 1025-Lead HSBGA (Heat Slug Ball Grid Array) Package

Figure 2 shows the drawings for the 1025-lead HSBGA thermally enhanced package being used for the GW80314 device.

Figure 2. 1025-Lead HSBGA Package Drawing

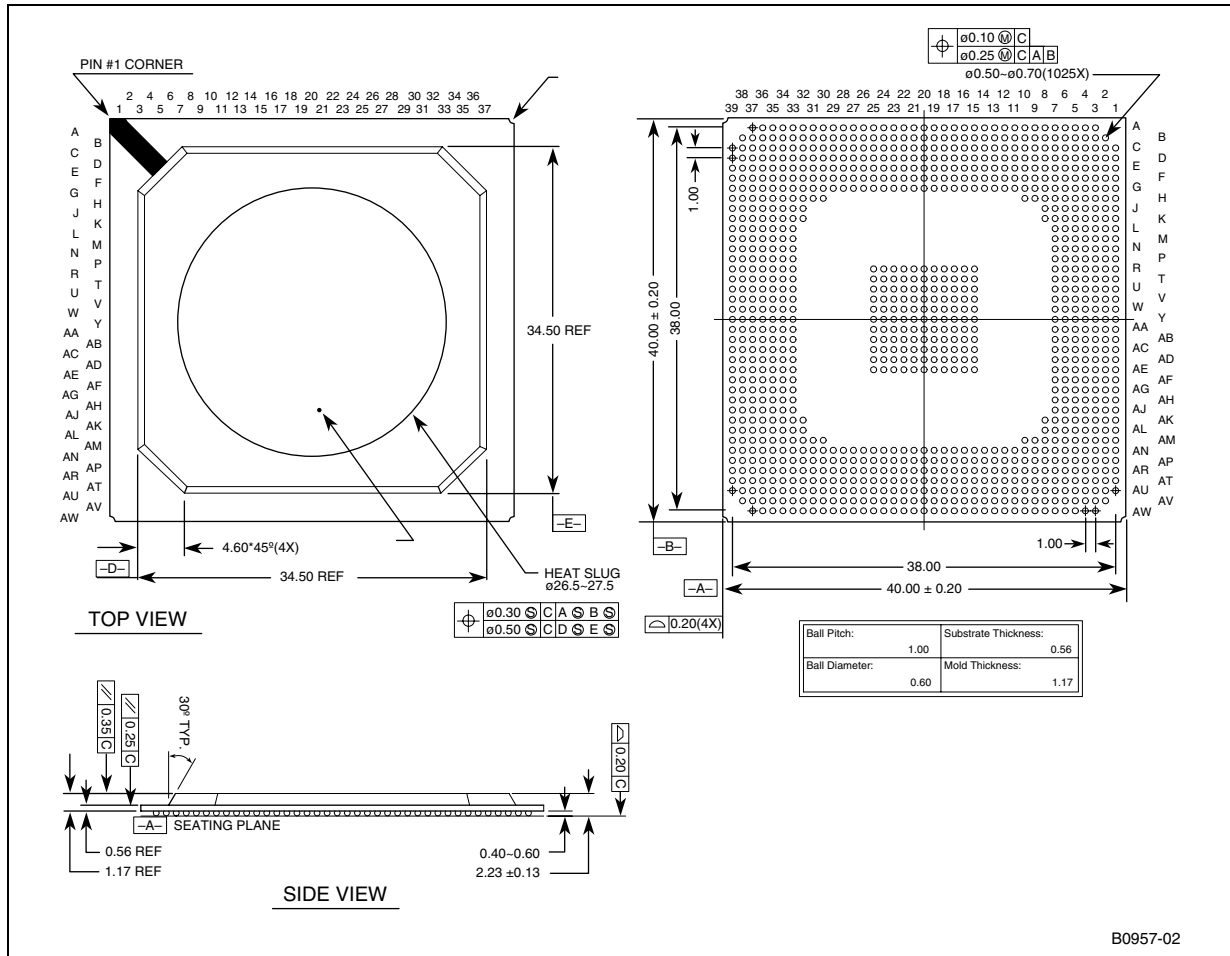


Figure 3. Ball Map - Left Side - Top View

Top View (Left Side)																						
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20		
A	NB	NB	E0_ECMDT	E0_TCG[5]	E0_TCG[3]	SD_DQ[6]	SD_DQ[6]	SD_VREF	SD_DQS[7]	SD_DQ[57]	SD_DQ[60]	SD_DQ[46]	SD_CAS#	SD_CS#0	SD_CS#2	SD_WE#	SD_BA[0]	SD_CLK[3]	SD_BA[1]	SD_A[0]	A	
B	NB	VSS_IO	VSS_IO	E0_TCG[1]	MDIO	E0_TCG[9]	VSS_IO	SD_DQ[62]	SD_CLKEN	VSS_IO	SD_DQ[56]	SD_DQ[43]	VSS_IO	SD_CS#1	SD_CS#3	VSS_IO	SD_RAS#	SD_CLK#3	VSS_IO	SD_A[10]	B	
C	E0_RCQ[3]	VSS_IO	VSS_IO	E0_PMA_CLK1	MDC	E0_PCHS_PASS	E0_TCG[2]	SD_DQS[15]	SD_DQ[58]	SD_DQ[53]	SD_DQ[48]	SD_DQ[35]	SD_DQ[38]	SD_DQ[14]	SD_DQ[4]	SD_DQ[37]	SD_DQ[37]	SD_ECC[3]	SD_ECC[2]	SD_DQ[58]	C	
D	E0_PCHL_RBCM	E0_T_CQ[7]	E0_PCHS_SD	VSS_IO	E0_PCHS_PASS	E0_TCG[2]	E0_TCG[8]	SD_DQ[52]	SD_DQ[54]	SD_DQ[55]	SD_DQ[50]	SD_DQ[51]	SD_DQ[39]	VSS_IO	SD_DQS[13]	SD_DQ[33]	VSS_IO	SD_ECC[7]	SD_DQ[31]	SD_DQ[17]	D	
E	E0_RCQ[1]	E0_EWRAP	E0_TCG[4]	E0_TCG[0]	E0_RCQ[0]	VSS_IO	E1_PCHL_RBCM	VSS_IO	SD_DQ[59]	SD_DQ[516]	VSS_IO	SD_DQ[47]	SD_DQ[35]	SD_DQ[34]	SD_DQ[45]	SD_DQ[44]	SD_ECC[7]	SD_DQ[31]	SD_DQ[17]	SD_ECC_DM[1]	E	
F	E0_RCQ[4]	E0_RCQ[6]	E1_TCG[5]	E0_RCQ[2]	VCC_PC	VCC_CORE	E0_TCG[9]	VCC_SD	VCC_SD	VCC_SD	SD_DQ[61]	SD_DQ[42]	SD_DQ[41]	VSS_IO	SD_DQ[40]	SD_DQ[36]	VSS_IO	SD_DQ[38]	SD_DQ[33]		F	
G	E0_RCQ[8]	E0_RCQ[9]	VSS_IO	E1_TCG[9]	E0_PMA_CLK0	VCC_PC	VCC_CORE	VCC_CORE	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	G	
H	E0_RCQ[7]	E1_TCG[3]	E1_TCG[4]	E1_TCG[1]	E1_TCG[7]	VCC_PC	VCC_CORE	VCC_CORE	VCC_CORE	VCC_CORE	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	H	
J	E1_TCG[2]	E1_PMA_CLK1	E1_RCQ[2]	E1_TCG[8]	E1_TCG[0]	VCC_PC	VCC_CORE	VCC_CORE	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	J	
K	E1_TCG[6]	E1_EWRAP	VSS_IO	REF_125M	E1_RCQ[5]	VCC_PC	VCC_CORE	VCC_CORE	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	K	
L	P2_INTD#	E1_RCQ[1]	E1_RCQ[0]	GTx_CLK	E1_PCHS_PASS	NC_L6	VCC_CORE	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	L	
M	P2_GNT#1	P2_REQ#1	E1_PMA_CLK0	E1_RCQ[4]	E1_RCQ[7]	VSS_IO	VCC_PC	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	M	
N	VSS_IO	P2_INTB#	E1_PCHS_SDET	E1_RCQ[3]	E1_PCHS_PASS	NC_N6	VCC_PC	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	N	
P	P2_AD[3]	P2_RST#	P2_INTA#	E0_ECMDT	E1_RCQ[8]	E1_RCQ[9]	VCC_PC	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	P	
R	P2_AD[26]	P2_HEALTHY#	P2_IDSEL	P2_AD[30]	VSS_IO	E1_RCQ[9]	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	R	
T	P2_PME#	P2_AD[27]	P2_AD[28]	P2_AD[24]	P2_CLK_IN	P2_PLL_AVSS	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	T	
U	P2_AD[21]	VSS_IO	P2_INTC#	P2_IRDY#	VSS_IO	P2_CLK_OUT	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	U	
V	P2_CBE#3	P2_CBE#1	P2_AD[25]	P2_AD[29]	P2_AD[23]	P2_PLL_AVCC	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	V	
W	P2_AD[22]	P2_SERR#	P2_AD[20]	P2_AD[18]	VSS_IO	P2_DEVSEL#	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VSS_CORE	VCC_CORE	VSS_CORE	VSS_CORE	VCC_CORE	VSS_CORE	W	
Y	P2_CBE#2	VSS_IO	P2_AD[19]	P2_FRAME#	P2_AD[15]	P2_TRDY#	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	Y	
AA	P2_AD[16]	P2_AD[17]	P2_PEER#	P2_PAR	P2_RSTDIR	P2_STOP#	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VSS_CORE	VCC_CORE	VSS_CORE	VSS_CORE	VCC_CORE	VSS_CORE	AA	
AB	P2_ACK6#	P2_AD[12]	P2_AD[13]	P2_AD[9]	VSS_IO	P2_AD[14]	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	AB	
AC	P2_AD[10]	VSS_IO	P2_CBE_B[0]	P2_AD[3]	P2_AD[8]	P2_AD[11]	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	AC	
AD	P2_AD[5]	P2_MMEN	P2_AD[6]	P2_AD[4]	P2_CBE_B[7]	P2_AD[7]	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	AD	
AE	P2_CBE#6	P2_AD[11]	P2_AD[0]	P2_REQ_B[3]	VSS_IO	P2_AD[2]	VCC_PC	NB	NB	NB	NB	NB	NB	NB	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	AE	
AF	P2_REQ#4	VSS_IO	P2_GNT_B[2]	P2_REQ#5	P2_GNT_B[4]	P2_ENUM#	VCC_PC	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	AF	
AG	P2_CBE#4	P2_GNT#5	P2_GNT_B[3]	P2_AD[61]	VSS_IO	P2_REQ#2	VCC_PC	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	AG	
AH	P2_AD[59]	VSS_IO	P2_AD[63]	P2_AD[62]	P2_AD[58]	P2_PAR64	VCC_PC	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	AH	
AJ	P2_AD[55]	P2_AD[60]	P2_AD[56]	P2_AD[53]	VSS_IO	P2_CBE#5	VCC_PC	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	AJ	
AK	P2_AD[50]	VSS_IO	P2_REQ64#	P2_AD[54]	P2_AD[49]	P2_AD[57]	VCC_PC	VCC_CORE	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	AK	
AL	P2_AD[46]	P2_AD[51]	P2_AD[44]	P2_AD[43]	VSS_IO	P2_AD[53]	VCC_PC	VCC_CORE	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	AL	
AM	P2_AD[45]	VSS_IO	P2_AD[47]	P2_AD[40]	P2_AD[39]	P2_AD[48]	VCC_PC	VCC_CORE	VCC_CORE	VCC_CORE	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	AM	
AN	P2_AD[37]	P2_AD[41]	P2_AD[35]	P2_LED#	VSS_IO	P2_AD[42]	VSS_IO	VCC-PC	VCC-PC	VCC-PC	VCC-PC	VCC-PC	VCC-PC	VCC-PC	VCC-PC	VCC-PC	VCC-PC	VCC-PC	VCC-PC	VCC-PC	AN	
AP	P2_AD[34]	VSS_IO	P2_AD[38]	P2_AD[32]	P2_AD[30]	P2_AD[36]	P1_PLL_AVSS	P1_CLK_OUT	P1_TRDY#	P1_STOP#	P1_AD[14]	P1_AD[11]	P1_AD[7]	P1_AD[2]	P1_ENUM	P1_REQ#4	P1_PAR64	P1_CBE#5	P1_AD[57]	AP		
AR	P2_GNT#6	P2_REQ#7	P2_REQ_B[6]	P2_GNT#7	VSS_IO	P1_AD[29]	P1_CLK_IN	P1_DEVSEL_B	VSS_IO	P1_FRAME#	VSS_IO	P1_RSTDIR	VSS_IO	P1_AD[9]	P1_AD[3]	VSS_IO	P1_GNT#4	VSS_IO	P1_AD[61]	VSS_IO	AR	
AT	P2_HS_64EN#	P2_PCHCAP[1]	VSS_IO	P1_IDSEL	P1_RST#	P1_GNT#1	P1_AD[30]	P1_AD[24]	P1_IRDY#	P1_AD[18]	P1_PAR	P1_AD[15]	P1_AD[9]	P1_AD[8]	P1_REQ#2	P1_REQ#5	P1_CBE#7	P1_AD[62]	P1_AD[58]	AT		
AU	P2_ES	VSS_IO	VSS_IO	P1_IDSEL	P1_INTA#	P1_INTB#	P1_INTC#	P1_AD[25]	P1_AD[20]	P1_AD[19]	P1_AD[12]	P1_AD[13]	P1_AD[6]	P1_CBE#0	P1_GNT#5	P1_AD[9]	P1_AD[3]	P1_GNT#3	P1_CBE#4	P1_AD[56]	AU	
AV	NB	VSS_IO	VSS_IO	P1_INTD#	P1_INTA#	P1_INTB#	VSS_IO	P1_CBE_B[1]	P1_SERR#	VSS_IO	P1_AD[17]	VSS_IO	P1_MMEN	VSS_IO	P1_AD[11]	VSS_IO	P1_GNT#2	VSS_IO	P1_AD[60]	VSS_IO	P1_AD[51]	AV
AW	NB	NB	P1_REQ#1	P1_INTA#	P1_INTB#	P1_AD[21]	P1_AD[31]	P1_AD[26]	P1_PME#	P1_PERR#	P1_CBE#3	P1_AD[22]	P1_CBE#2	P1_AD[16]	P1_ACK64#	P1_AD[10]	P1_AD[5]	P1_REQ#3	P1_CBE#6	P1_REQ64#	AW	
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20		

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Figure 4. Ball Map - Right Side - Top View

Top View (Right Side)

	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	37	38	39		
A	SD_CLK[0]	SD_A[1]	SD_CLK[1]	SD_CLK[2]	SD_A[2]	SD_A[4]	SD_A[5]	SD_A[8]	SD_A[9]	SD_A[12]	SD_DQ[1]	SD_I2C_SDA	SD_DQ[8]	SD_CKFBI	SD_CS[4]	SD_CS[7]	SD_CS[6]	NB	NB	A	
B	SD_CLK[0]	VSS_IO	SD_CLK[1]	SD_CLK[2]	VSS_IO	SD_A[3]	SD_A[6]	VSS_IO	SD_A[7]	SD_A[11]	VSS_IO	SD_A[13]	SD_CS[5]	VSS_IO	SD_CKFBO	PBI_AD[29]	VSS_IO	VSS_IO	NB	B	
C	SD_DQ[26]	SD_DQ[28]	SD_DQ[25]	SD_DQ[1]	SD_DQ[18]	SD_DQ[23]	SD_DQ[21]	SD_DQ[20]	SD_DQ[2]	SD_DQ[6]	SD_DQ[5]	SD_I2C_CLK	SD_PWR_DELAY	SD_DQ[4]	PBI_AD[31]	PBI_AD[27]	VSS_IO	VSS_IO	PBI_AD[24]	C	
D	SD_DQ[12]	SD_DQ[29]	VSS_IO	SD_DQ[24]	SD_DQ[10]	VSS_IO	SD_DQ[10]	VSS_IO	SD_DQ[13]	VSS_IO	SD_DQ[8]	SD_DQ[0]	SD_PLL_AVSS	PBI_AD[4]	PBI_CS[3]	PBI_AD[28]	VSS_IO	PBI_AD[23]	PBI_AD[25]	PBI_AD[19]	D
E	SD_ECC[5]	SD_ECC[4]	SD_DQ[19]	SD_DQ[22]	SD_DQ[15]	SD_DQ[14]	SD_DQ[16]	SD_DQ[3]	SD_DQ[0]	SD_DQ[7]	SD_DQ[5]	VSS_IO	PBI_AD[26]	PBI_AD[21]	VSS_IO	PBI_AD[22]	PBI_AD[18]	PBI_AD[20]	VSS_IO	E	
F	VSS_IO	SD_ECC[0]	SD_DQ[23]	VSS_IO	SD_DQ[11]	SD_DQ[17]	VSS_IO	SD_DQ[8]	SD_DQ[12]	VSS_IO	VCC_SD	PBI_AD[30]	VCC_XS	VCC_XS	PBI_CS[0]	PBI_AD[15]	PBI_CS[1]	PBI_AD[20]	PBI_AD[17]	F	
G	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	VCC_SD	SD_PLL_AVCC	VCC_SD	PBI_LE	VCC_XS	VCC_XS	PBI_CS[2]	PBI_AD[14]	VSS_IO	PBI_AD[16]	PBI_AD[13]	G	
H	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VCC_CORE	VCC_CORE	VCC_XS	VCC_XS	PBI_AD[5]	PBI_AD[13]	PBI_AD[5]	PBI_AD[12]	PBI_AD[1]	H	
J	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VCC_XS	VCC_XS	NC_X35	PBI_OE	PBI_AD[8]	XS_DQ[48]	VSS_IO	J	
K	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VCC_XS	VCC_XS	NC_X34	PBI_RDY	PBI_AD[0]	XS_C_CLK	XS_DQ[51]	K	
L	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	XS_PLL_AVCC	PBI_AD[2]	VSS_IO	XS_DQ[50]	XS_DQ[52]	XS_DQ[20]	XS_DQ[53]	L		
M	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	XS_PLL_DUMMY	XS_PLL_AVSS	PBI_AD[3]	XS_DQ[55]	XS_DQ[54]	VSS_IO	XS_DQ[23]	M		
N	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_XS	PBI_AD[6]	VSS_IO	XS_DQ[19]	XS_DQ[18]	XS_DQ[16]	XS_DQ[22]	N		
P	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_XS	PBI_AD[7]	PBI_AD[1]	XS_DQ[17]	XS_DQ[21]	VSS_IO	XS_DQ[47]	P		
R	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	NB	NB	NB	NB	NB	NB	NB	XS_DQ[45]	VSS_IO	XS_DQ[43]	XS_DQ[46]	XS_DQ[40]	XS_DQ[44]	R		
T	VCC_CORE	VSS_CORE	VCC_CORE	VCC_CORE	VCC_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_DQ[41]	XS_DQ[10]	XS_DQ[42]	XS_DQ[14]	VSS_IO	XS_DQ[15]	T		
U	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_DQ[13]	VSS_IO	XS_DQ[11]	XS_DQ[9]	XS_DQ[39]	XS_DQ[12]	U		
V	VSS_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_DQ[38]	XS_DQ[34]	XS_DQ[36]	VSS_IO	XS_DQ[36]	VSS_IO	V		
W	VSS_CORE	VSS_CORE	VSS_CORE	VCC_CORE	VSS_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_DQ[37]	VSS_IO	XS_DQ[35]	XS_DQ[7]	XS_DQ[3]	XS_DQ[32]	W		
Y	VSS_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_DQ[6]	XS_DQ[0]	XS_DQ[2]	XS_DQ[1]	VSS_IO	XS_DQ[4]	Y		
AA	VSS_CORE	VSS_CORE	VSS_CORE	VCC_CORE	VSS_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_DQ[5]	VSS_IO	XS_DVALID[0]	XS_ECC[2]	XS_ECC[0]	XS_ECC[1]	AA		
AB	VSS_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_DVALID[1]	XS_ECC[3]	XS_ECC[5]	XS_ECC[7]	VSS_IO	XS_ECC[6]	AB		
AC	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_ECC[4]	VSS_IO	XS_BE[0]	XS_BE[2]	XS_BE[5]	XS_BE[3]	AC		
AD	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_BE[1]	XS_LEN[2]	LEN[0]	XS_LEN[1]	VSS_IO	XS_BE[4]	AD		
AE	VSS_CORE	VCC_CORE	VSS_CORE	VCC_CORE	VSS_CORE	NB	NB	NB	NB	NB	NB	VCC_XS	XS_BE[6]	VSS_IO	XS_BE[7]	XS_CWF	XS_HLDA[1]	XS_HOLD[0]	AE		
AF	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_XS	XS_ABORT	XS_A[13]	XS_A[4]	XS_A[8]	VSS_IO	XS_HOLD[1]	AF		
AG	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_XS	XS_HLDA[0]	VSS_IO	XS_A[12]	XS_A[3]	XS_A[1]	XS_A[5]	AG		
AH	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_XS	XS_A[0]	XS_A[14]	XS_A[14]	XS_A[6]	VSS_IO	XS_A[7]	AH		
AJ	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_XS	XS_A[5]	VSS_IO	XS_A[10]	XS_DQ[56]	XS_DQ[59]	XS_A[15]	AJ		
AK	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VCC_XS	XS_A[9]	XS_DQ[60]	XS_DQ[57]	XS_DQ[61]	VSS_IO	XS_DQ[62]	AK	
AL	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VCC_PC	U1_DTR	VSS_IO	XS_DQ[58]	XS_DQ[30]	XS_DQ[27]	XS_DQ[29]	AL	
AM	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	NB	VCC_CORE	VCC_CORE	U0_DCD	U0_DTR	XS_DQ[63]	XS_DQ[31]	VSS_IO	XS_DQ[28]	AM	
AN	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	VCC_PC	U1_DSR	VSS_IO	U0_DSR	XS_DQ[25]	XS_DQ[24]	AN
AP	P1_AD[52]	P1_AD[48]	P1_AD[42]	P1_REQ[7]	SF_RST	PWRUP_P1_ARB	PWRUP_TRANS	TDO	VCC_PC	VCC_PC	VCC_PC	INT[5]	VSS_IO	VSS_IO	U0_RX	U1_RX	U1_CTS	XS_IRQ[1]	XS_IRQ[0]	AP	
AR	P1_AD[53]	VSS_IO	P1_AD[43]	VSS_IO	PWRUP_P1_PRRM	PWRUP_P1_SWRST	TRST	VSS_IO	NC	INT[1]	NC	INT[11]	NC	INT[12]	NC	INT[14]	I2C_SCLX	VSS_IO	U1_RTS	XS_C_FIQ[0]	AR
AT	P1_AD[54]	P1_AD[49]	P1_AD[44]	P1_GNT[7]	P1_GNT[8]	P1_LED	P1_HS_64EN	TMS	TCK	NC	NC	NC	NC	INT[7]	INT[14]	I2C_SCLX	VSS_IO	U1_RTS	U0_RI	XS_RESET	AT
AU	P1_AD[46]	P1_AD[47]	P1_AD[38]	P1_AD[40]	VSS_IO	P1_AD[34]	P1_AD[35]	P1_ES	P1_AD[32]	PWRUP_P2_PRRM	TDI	INT[2]	VSS_IO	NT[6]	INT[13]	INT[15]	PWRUP_P2_PV	VSS_IO	VSS_IO	U1_DCD	AU
AV	VSS_IO	P1_AD[41]	P1_REQ[6]	VSS_IO	VSS_IO	P1_PCICAP	P1_PCICAP	P1_AD[33]	VSS_IO	INT[6]	INT[3]	PWRUP_P1_PRRM	INT[10]	INT[8]	INT[12]	U1_TX	VSS_IO	VSS_IO	NB	NB	AV
AW	P1_AD[59]	P1_AD[55]	P1_AD[50]	P1_AD[45]	P1_AD[37]	PWRUP_P2_SWRST	P1_PCICAP	P1_PCICAP	PWRUP_P2_SWRST	PWRUP_P2_PRRM	P1_AD[36]	SF_CLK	INT[9]	NC	PWRUP_P2_ARB	NC	INT[4]	U1_RI	NB	NB	AW
	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	36	37	38	39		

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Table 20. 1025-Lead HSBGA Package - Alphabetical Ball Listings

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
A3	E0_ECMDT	B5	MDIO	C5	MDC
A4	E0_TCG[5]	B6	E0_TCG[9]	C6	E0_PRBSEN
A5	E0_TCG[3]	B7	VSS_IO	C7	SD_DQS[15]
A6	SD_DQ[63]	B8	SD_DQ[62]	C8	SD_DQ[58]
A7	SD_DQS[6]	B9	SD_CLKEN	C9	SD_DQ[53]
A8	SD_VREF	B10	VSS_IO	C10	SD_DQ[49]
A9	SD_DQS[7]	B11	SD_DQ[56]	C11	SD_DQ[48]
A10	SD_DQ[57]	B12	SD_DQ[43]	C12	SD_DQ[35]
A11	SD_DQ[60]	B13	VSS_IO	C13	SD_DQ[38]
A12	SD_DQ[46]	B14	SD_CS#[1]	C14	SD_DQS[14]
A13	SD_CAS#	B15	SD_CS#[3]	C15	SD_DQS[4]
A14	SD_CS#[0]	B16	VSS_IO	C16	SD_DQ[37]
A15	SD_CS#[2]	B17	SD_RAS#	C17	SD_DQ[32]
A16	SD_WE#	B18	SD_CLK#[3]	C18	SD_ECC[3]
A17	SD_BA[0]	B19	VSS_IO	C19	SD_ECC[2]
A18	SD_CLK[3]	B20	SD_A[10]	C20	SD_DQS[8]
A19	SD_BA[1]	B21	SD_CLK#[0]	C21	SD_DQ[26]
A20	SD_A[0]	B22	VSS_IO	C22	SD_DQ[28]
A21	SD_CLK[0]	B23	SD_CLK#[1]	C23	SD_DQ[25]
A22	SD_A[1]	B24	SD_CLK#[2]	C24	SD_DQ[11]
A23	SD_CLK[1]	B25	VSS_IO	C25	SD_DQ[18]
A24	SD_CLK[2]	B26	SD_A[3]	C26	SD_DQS[2]
A25	SD_A[2]	B27	SD_A[6]	C27	SD_DQ[21]
A26	SD_A[4]	B28	VSS_IO	C28	SD_DQ[20]
A27	SD_A[5]	B29	SD_A[7]	C29	SD_DQ[2]
A28	SD_A[8]	B30	SD_A[11]	C30	SD_DQ[6]
A29	SD_A[9]	B31	VSS_IO	C31	SD_DQS[9]
A30	SD_A[12]	B32	SD_A[13]	C32	SD_I2C_CLK
A31	SD_DQ[1]	B33	SD_CS#[5]	C33	SD_PWRDELAY
A32	SD_I2C_SDA	B34	VSS_IO	C34	SD_DQ[4]
A33	SD_DQ[8]	B35	SD_CKFBO	C35	PBI_AD[31]
A34	SD_CKFBI	B36	PBI_AD[29]	C36	PBI_AD[27]
A35	SD_CS#[4]	B37	VSS_IO	C37	VSS_IO
A36	SD_CS#[7]	B38	VSS_IO	C38	VSS_IO
A37	SD_CS#[6]	C1	E0_RCG[3]	C39	PBI_AD[24]
B2	VSS_IO	C2	VSS_IO	D1	E0_PCOL_RBCM
B3	VSS_IO	C3	VSS_IO	D2	E0_TCG[7]
B4	E0_TCG[1]	C4	E0_PMA_CLK1	D3	E0_PCRS_SDET

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
D4	VSS_IO	E4	E0_TCG[0]	F4	E0_RCG[6]
D5	E0_PRBS_PASS	E5	E0_RCG[0]	F5	E0_RCG[2]
D6	E0_TCG[2]	E6	VSS_IO	F6	VCC_PC
D7	E0_TCG[8]	E7	E1_PCOL_RBCM	F7	VCC_CORE
D8	SD_DQ[52]	E8	VSS_IO	F8	E0_TCG[6]
D9	SD_DQ[54]	E9	SD_DQ[59]	F9	VCC_SD
D10	SD_DQ[55]	E10	SD_DQS[16]	F10	VCC_SD
D11	SD_DQ[50]	E11	VSS_IO	F11	VCC_SD
D12	SD_DQ[51]	E12	SD_DQ[47]	F12	SD_DQ[61]
D13	SD_DQ[39]	E13	SD_DQS[5]	F13	SD_DQ[42]
D14	VSS_IO	E14	SD_DQ[34]	F14	SD_DQ[41]
D15	SD_DQS[13]	E15	SD_DQ[45]	F15	VSS_IO
D16	SD_DQ[33]	E16	SD_DQ[44]	F16	SD_DQ[40]
D17	VSS_IO	E17	SD_ECC[7]	F17	SD_DQ[36]
D18	SD_ECC[6]	E18	SD_DQ[31]	F18	VSS_IO
D19	SD_DQ[27]	E19	SD_DQS[17]	F19	SD_DQ[30]
D20	VSS_IO	E20	SD_ECC[1]	F20	SD_DQS[3]
D21	SD_DQS[12]	E21	SD_ECC[5]	F21	VSS_IO
D22	SD_DQ[29]	E22	SD_ECC[4]	F22	SD_ECC[0]
D23	VSS_IO	E23	SD_DQ[19]	F23	SD_DQ[23]
D24	SD_DQ[24]	E24	SD_DQ[22]	F24	VSS_IO
D25	SD_DQ[10]	E25	SD_DQ[15]	F25	SD_DQS[11]
D26	VSS_IO	E26	SD_DQ[14]	F26	SD_DQ[17]
D27	SD_DQS[10]	E27	SD_DQ[16]	F27	VSS_IO
D28	SD_DQ[13]	E28	SD_DQ[3]	F28	SD_DQS[1]
D29	VSS_IO	E29	SD_DQS[0]	F29	SD_DQ[12]
D30	SD_DQ[9]	E30	SD_DQ[7]	F30	VSS_IO
D31	SD_DQ[0]	E31	SD_DQ[5]	F31	VCC_SD
D32	SD_PLL_AVSS	E32	VSS_IO	F32	PBI_AD[30]
D33	PBI_AD[4]	E33	PBI_AD[26]	F33	VCC_XS
D34	PBI_CS#[3]	E34	PBI_AD[21]	F34	VCC_XS
D35	PBI_AD[28]	E35	VSS_IO	F35	PBI_CS#[0]
D36	VSS_IO	E36	PBI_AD[22]	F36	PBI_AD[15]
D37	PBI_AD[23]	E37	PBI_AD[18]	F37	PBI_CS#[1]
D38	PBI_AD[25]	E38	PBI_AD[20]	F38	PBI_RW
D39	PBI_AD[19]	E39	VSS_IO	F39	PBI_AD[17]
E1	E0_RCG[1]	F1	E0_RCG[4]	G1	E0_RCG[8]
E2	E0_EWRAP	F2	E0_RCG[5]	G2	E0_RCG[9]
E3	E0_TCG[4]	F3	E1_TCG[5]	G3	VSS_IO

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
G4	E1_TCG[9]	H4	E1_TCG[1]	K7	VCC_CORE
G5	E0_PMA_CLK0	H5	E1_TCG[7]	K8	VCC_CORE
G6	VCC_PC	H6	VCC_PC	K32	VCC_CORE
G7	VCC_CORE	H7	VCC_PC	K33	VCC_XS
G8	VCC_CORE	H8	VCC_CORE	k34	NC_K34
G9	VCC_SD	H9	VCC_CORE	K35	PBI_RDY#
G10	VCC_SD	H10	VCC_CORE	K36	PBI_AD[0]
G11	VCC_SD	H30	VCC_CORE	K37	XS_DQ[49]
G12	VCC_SD	H31	VCC_CORE	K38	XS_CLK
G13	VCC_SD	H32	VCC_CORE	K39	XS_DQ[51]
G14	VCC_SD	H33	VCC_XS	L1	P2_INTD#
G15	VCC_SD	H34	VCC_XS	L2	E1_RCG[1]
G16	VCC_SD	H35	PBI_AD[9]	L3	E1_RCG[0]
G17	VCC_SD	H36	PBI_AD[10]	L4	GTX_CLK
G18	VCC_SD	H37	PBI_AD[5]	L5	E1_PRBSEN
G19	VCC_SD	H38	PBI_AD[12]	L6	NC_L6
G20	VCC_SD	H39	PBI_AD[11]	L7	VCC_CORE
G21	VCC_SD	J1	E1_TCG[2]	L33	XS_PLL_AVCC
G22	VCC_SD	J2	E1_PMA_CLK1	L34	PBI_AD[2]
G23	VCC_SD	J3	E1_RCG[2]	L35	VSS_IO
G24	VCC_SD	J4	E1_TCG[8]	L36	XS_DQ[50]
G25	VCC_SD	J5	E1_TCG[0]	L37	XS_DQ[52]
G26	VCC_SD	J6	VCC_PC	L38	XS_DQ[20]
G27	VCC_SD	J7	VCC_CORE	L39	XS_DQ[53]
G28	VCC_SD	J8	VCC_CORE	M1	P2_GNT#[1]
G29	VCC_SD	J32	VCC_CORE	M2	P2_REQ#[1]
G30	SD_PLL_AVCC	J33	VCC_XS	M3	E1_PMA_CLK0
G31	VCC_SD	J34	VCC_XS	M4	E1_RCG[4]
G32	PBI_LE	J35	NC_J35	M5	E1_RCG[7]
G33	VCC_XS	J36	PBI_OE#	M6	VSS_IO
G34	VCC_XS	J37	PBI_AD[8]	M7	VCC_PC
G35	PBI_CS#[2]	J38	XS_DQ[48]	M33	NC_M33
G36	PBI_AD[14]	J39	VSS_IO	M34	XS_PLL_AVSS
G37	VSS_IO	K1	E1_TCG[6]	M35	PBI_AD[3]
G38	PBI_AD[16]	K2	E1_EWRAP	M36	XS_DQ[55]
G39	PBI_AD[13]	K3	VSS_IO	M37	XS_DQ[54]
H1	E0_RCG[7]	K4	REF125M	M38	VSS_IO
H2	E1_TCG[3]	K5	E1_RCG[5]	M39	XS_DQ[23]
H3	E1_TCG[4]	K6	VCC_PC	N1	P2_INTB#

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
N2	VSS_IO	R20	VCC_CORE	U2	VSS_IO
N3	E1_PCRS_SDET	R21	VSS_CORE	U3	P2_INTC#
N4	E1_RCG[3]	R22	VCC_CORE	U4	P2_IRDY#
N5	E1_PRBS_PASS	R23	VSS_CORE	U5	VSS_IO
N6	NC_N6	R24	VCC_CORE	U6	P2_CLK_OUT
N7	VCC_PC	R25	VSS_CORE	U7	VCC_PC
N33	VCC_XS	R33	VCC_XS	U15	VSS_CORE
N34	PBI_AD[6]	R34	XS_DQ[45]	U16	VCC_CORE
N35	VSS_IO	R35	VSS_IO	U17	VSS_CORE
N36	XS_DQ[19]	R36	XS_DQ[43]	U18	VCC_CORE
N37	XS_DQ[18]	R37	XS_DQ[46]	U19	VSS_CORE
N38	XS_DQ[16]	R38	XS_DQ[40]	U20	VCC_CORE
N39	XS_DQ[22]	R39	XS_DQ[44]	U21	VSS_CORE
P1	P2_AD[31]	T1	P2_PME#	U22	VCC_CORE
P2	P2_RST#	T2	P2_AD[27]	U23	VSS_CORE
P3	P2_INTA#	T3	P2_AD[28]	U24	VCC_CORE
P4	E1_ECMDT	T4	P2_AD[24]	U25	VSS_CORE
P5	E1_RCG[8]	T5	P2_CLK_IN	U33	VCC_XS
P6	E1_RCG[6]	T6	P2_PLL_AVSS	U34	XS_DQ[13]
P7	VCC_PC	T7	VCC_PC	U35	VSS_IO
P33	VCC_XS	T15	VCC_CORE	U36	XS_DQ[11]
P34	PBI_AD[7]	T16	VSS_CORE	U37	XS_DQ[9]
P35	PBI_AD[1]	T17	VCC_CORE	U38	XS_DQ[39]
P36	XS_DQ[17]	T18	VSS_CORE	U39	XS_DQ[12]
P37	XS_DQ[21]	T19	VCC_CORE	V1	P2_CBE#[3]
P38	VSS_IO	T20	VSS_CORE	V2	P2_CBE#[1]
P39	XS_DQ[47]	T21	VCC_CORE	V3	P2_AD[25]
R1	P2_AD[26]	T22	VSS_CORE	V4	P2_AD[29]
R2	P2_HEALTHY#	T23	VCC_CORE	V5	P2_AD[23]
R3	P2_IDSEL	T24	VSS_CORE	V6	P2_PLL_AVCC
R4	P2_AD[30]	T25	VCC_CORE	V7	VCC_PC
R5	VSS_IO	T33	VCC_XS	V15	VCC_CORE
R6	E1_RCG[9]	T34	XS_DQ[41]	V16	VSS_CORE
R7	VCC_PC	T35	XS_DQ[10]	V17	VCC_CORE
R15	VSS_CORE	T36	XS_DQ[42]	V18	VSS_CORE
R16	VCC_CORE	T37	XS_DQ[14]	V19	VSS_CORE
R17	VSS_CORE	T38	VSS_IO	V20	VSS_CORE
R18	VCC_CORE	T39	XS_DQ[15]	V21	VSS_CORE
R19	VSS_CORE	U1	P2_AD[21]	V22	VSS_CORE

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
V23	VCC_CORE	Y5	P2_AD[15]	AA33	VCC_XS
V24	VSS_CORE	Y6	P2_TRDY#	AA34	XS_DQ[5]
V25	VCC_CORE	Y7	VCC_PC	AA35	VSS_IO
V33	VCC_XS	Y15	VCC_CORE	AA36	XS_DVALID[0]
V34	XS_DQ[8]	Y16	VSS_CORE	AA37	XS_ECC[2]
V35	XS_DQ[38]	Y17	VCC_CORE	AA38	XS_ECC[0]
V36	XS_DQ[34]	Y18	VSS_CORE	AA39	XS_ECC[1]
V37	XS_DQ[33]	Y19	VSS_CORE	AB1	P2_ACK64#
V38	VSS_IO	Y20	VSS_CORE	AB2	P2_AD[12]
V39	XS_DQ[36]	Y21	VSS_CORE	AB2	VSS_CORE
W1	P2_AD[22]	Y22	VSS_CORE	AB3	P2_AD[13]
W2	P2_SERR#	Y23	VCC_CORE	AB4	P2_AD[9]
W3	P2_AD[20]	Y24	VSS_CORE	AB5	VSS_IO
W4	P2_AD[18]	Y25	VCC_CORE	AB6	P2_AD[14]
W5	VSS_IO	Y33	VCC_XS	AB7	VCC_PC
W6	P2_DEVSEL#	Y34	XS_DQ[6]	AB15	VCC_CORE
W7	VCC_PC	Y35	XS_DQ[0]	AB16	VSS_CORE
W15	VSS_CORE	Y36	XS_DQ[2]	AB17	VCC_CORE
W16	VCC_CORE	Y37	XS_DQ[1]	AB18	VSS_CORE
W17	VSS_CORE	Y38	VSS_IO	AB19	VSS_CORE
W18	VSS_CORE	Y39	XS_DQ[4]	AB20	VSS_CORE
W19	VSS_CORE	AA1	P2_AD[16]	AB21	VSS_CORE
W20	VSS_CORE	AA2	P2_AD[17]	AB23	VCC_CORE
W21	VSS_CORE	AA3	P2_PERR#	AB24	VSS_CORE
W22	VSS_CORE	AA4	P2_PAR	AB25	VCC_CORE
W23	VSS_CORE	AA5	P2_RSTDIR	AB33	VCC_XS
W24	VCC_CORE	AA6	P2_STOP#	AB34	XS_DVALID[1]
W25	VSS_CORE	AA7	VCC_PC	AB35	XS_ECC[3]
W33	VCC_XS	AA15	VSS_CORE	AB36	XS_ECC[5]
W34	XS_DQ[37]	AA16	VCC_CORE	AB37	XS_ECC[7]
W35	VSS_IO	AA17	VSS_CORE	AB38	VSS_IO
W36	XS_DQ[35]	AA18	VSS_CORE	AB39	XS_ECC[6]
W37	XS_DQ[7]	AA19	VSS_CORE	AC1	P2_AD[10]
W38	XS_DQ[3]	AA20	VSS_CORE	AC2	VSS_IO
W39	XS_DQ[32]	AA21	VSS_CORE	AC3	P2_CBE#[0]
Y1	P2_CBE#[2]	AA22	VSS_CORE	AC4	P2_AD[3]
Y2	VSS_IO	AA23	VSS_CORE	AC5	P2_AD[8]
Y3	P2_AD[19]	AA24	VCC_CORE	AC6	P2_AD[11]
Y4	P2_FRAME#	AA25	VSS_CORE	AC7	VCC_PC

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
AC15	VSS_CORE	AD36	XS_LEN[0]	AF36	XS_A[4]
AC16	VCC_CORE	AD37	XS_LEN[1]	AF37	XS_A[8]
AC17	VSS_CORE	AD38	VSS_IO	AF38	VSS_IO
AC18	VCC_CORE	AD39	XS_BE[4]	AF39	XS_HOLD[1]
AC19	VSS_CORE	AE1	P2_CBE#[6]	AG1	P2_CBE#[4]
AC20	VCC_CORE	AE2	P2_AD[1]	AG2	P2_GNT#[5]
AC21	VSS_CORE	AE3	P2_AD[0]	AG3	P2_GNT#[3]
AC22	VCC_CORE	AE4	P2_REQ#[3]	AG4	P2_AD[61]
AC23	VSS_CORE	AE5	VSS_IO	AG5	VSS_IO
AC24	VCC_CORE	AE6	P2_AD[2]	AG6	P2_REQ#[2]
AC25	VSS_CORE	AE7	VCC_PC	AG7	VCC_PC
AC33	VCC_XS	AE15	VSS_CORE	AG33	VCC_XS
AC34	XS_ECC[4]	AE16	VCC_CORE	AG34	XS_HLDA[0]
AC35	VSS_IO	AE17	VSS_CORE	AG35	VSS_IO
AC36	XS_BE[0]	AE18	VCC_CORE	AG36	XS_A[12]
AC37	XS_BE[2]	AE19	VSS_CORE	AG37	XS_A[3]
AC38	XS_BE[5]	AE20	VCC_CORE	AG38	XS_A[1]
AC39	XS_BE[3]	AE21	VSS_CORE	AG39	XS_A[2]
AD1	P2_AD[5]	AE22	VCC_CORE	AH1	P2_AD[59]
AD2	P2_M66EN	AE23	VSS_CORE	AH2	VSS_IO
AD3	P2_AD[6]	AE24	VCC_CORE	AH3	P2_AD[63]
AD4	P2_AD[4]	AE25	VSS_CORE	AH4	P2_AD[62]
AD5	P2_CBE#[7]	AE33	VCC_XS	AH5	P2_AD[58]
AD6	P2_AD[7]	AE34	XS_BE[6]	AH6	P2_PAR64
AD7	VCC_PC	AE35	VSS_IO	AH7	VCC_PC
AD15	VCC_CORE	AE36	XS_BE[7]	AH33	VCC_XS
AD16	VSS_CORE	AE37	XS_CWF	AH34	XS_A[0]
AD17	VCC_CORE	AE38	XS_HLDA[1]	AH35	XS_A[11]
AD18	VSS_CORE	AE39	XS_HOLD[0]	AH36	XS_A[14]
AD19	VCC_CORE	AF1	P2_REQ#[4]	AH37	XS_A[6]
AD20	VSS_CORE	AF2	VSS_IO	AH38	VSS_IO
AD21	VCC_CORE	AF3	P2_GNT#[2]	AH39	XS_A[7]
AD22	VSS_CORE	AF4	P2_REQ#[5]	AJ1	P2_AD[55]
AD23	VCC_CORE	AF5	P2_GNT#[4]	AJ2	P2_AD[60]
AD24	VSS_CORE	AF6	P2_ENUM#	AJ3	P2_AD[56]
AD25	VCC_CORE	AF7	VCC_PC	AJ4	P2_AD[53]
AD33	VCC_XS	AF33	VCC_XS	AJ5	VSS_IO
AD34	XS_BE[1]	AF34	XS_ABORT	AJ6	P2_CBE#[5]
AD35	XS_LEN[2]	AF35	XS_A[13]	AJ7	VCC_PC

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
AJ33	VCC_XS	AM1	P2_AD[45]	AN20	VCC_PC
AJ34	XS_A[5]	AM2	VSS_IO	AN21	VCC_PC
AJ35	VSS_IO	AM3	P2_AD[47]	AN22	VCC_PC
AJ36	XS_A[10]	AM4	P2_AD[40]	AN23	VCC_PC
AJ37	XS_DQ[56]	AM5	P2_AD[39]	AN24	VCC_PC
AJ38	XS_DQ[59]	AM6	P2_AD[48]	AN25	VCC_PC
AJ39	XS_A[15]	AM7	VCC_PC	AN26	VCC_PC
AK1	P2_AD[50]	AM8	VCC_CORE	AN27	VCC_PC
AK2	VSS_IO	AM9	VCC_CORE	AN28	VCC_PC
AK3	P2_REQ64#	AM10	VCC_CORE	AN29	VCC_CORE
AK4	P2_AD[54]	AM30	VCC_CORE	AN30	VCC_PC
AK5	P2_AD[49]	AM31	VCC_CORE	AN31	VCC_PC
AK6	P2_AD[57]	AM32	VCC_CORE	AN32	VCC_PC
AK7	VCC_PC	AM33	VCC_PC	AN33	VCC_PC
AK8	VCC_CORE	AM34	U0_DCD#	AN34	U1_DSR#
AK32	VCC_CORE	AM35	U0_DTR#	AN35	VSS_IO
AK33	VCC_XS	AM36	XS_DQ[63]	AN36	U0_DSR#
AK34	XS_A[9]	AM37	XS_DQ[31]	AN37	XS_DQ[25]
AK35	XS_DQ[60]	AM38	VSS_IO	AN38	XS_DQ[24]
AK36	XS_DQ[57]	AM39	XS_DQ[28]	AN39	XS_DQ[26]
AK37	XS_DQ[61]	AN1	P2_AD[37]	AP1	P2_AD[34]
AK38	VSS_IO	AN2	P2_AD[41]	AP2	VSS_IO
AK39	XS_DQ[62]	AN3	P2_AD[35]	AP3	P2_AD[38]
AL1	P2_AD[46]	AN4	P2_LED#	AP4	P2_AD[32]
AL2	P2_AD[51]	AN5	VSS_IO	AP5	P2_AD[33]
AL3	P2_AD[44]	AN6	P2_AD[42]	AP6	P2_AD[36]
AL4	P2_AD[43]	AN7	VSS_IO	AP7	P1_PLL_AVSS
AL5	VSS_IO	AN8	VCC_PC	AP8	P1_CLK_OUT
AL6	P2_AD[52]	AN9	VCC_PC	AP9	P1_PLL_AVCC
AL7	VCC_PC	AN10	VCC_PC	AP10	P1_TRDY#
AL8	VCC_CORE	AN11	VCC_PC	AP11	P1_STOP#
AL32	VCC_CORE	AN12	VCC_PC	AP12	P1_AD[14]
AL33	VCC_XS	AN13	VCC_PC	AP13	P1_AD[11]
AL34	U1_DTR#	AN14	VCC_PC	AP14	P1_AD[7]
AL35	VSS_IO	AN15	VCC_PC	AP15	P1_AD[2]
AL36	XS_DQ[58]	AN16	VCC_PC	AP16	P1_ENUM#
AL37	XS_DQ[30]	AN17	VCC_PC	AP17	P1_REQ#[4]
AL38	XS_DQ[27]	AN18	VCC_PC	AP18	P1_PAR64
AL39	XS_DQ[29]	AN19	VCC_PC	AP19	P1_CBE#[5]

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
AP20	P1_AD[57]	AR20	VSS_IO	AT19	P1_AD[62]
AP21	P1_AD[52]	AR21	P1_AD[53]	AT20	P1_AD[58]
AP22	P1_AD[48]	AR22	VSS_IO	AT21	P1_AD[54]
AP23	P1_AD[42]	AR23	P1_AD[43]	AT22	P1_AD[49]
AP24	P1_REQ#[7]	AR24	VSS_IO	AT23	P1_AD[44]
AP25	SF_RST#	AR25	PWRUP_P1_PRIM	AT24	P1_GNT#[7]
AP26	PWRUP_P1_ARB	AR26	PWRUP_P1_SWRS T	AT25	P1_GNT#[6]
AP27	PWRUP_TRANS	AR27	TRST#	AT26	P1_LED#
AP28	TDO	AR28	VSS_IO	AT27	P1_HS_64EN#
AP29	VCC_PC	AR29	NC	AT28	TMS
AP30	VCC_PC	AR30	INT[1]	AT29	TCK
AP31	VCC_PC	AR31	NC	AT30	NC
AP32	INT[5]	AR32	INT[11]	AT31	NC
AP33	VSS_IO	AR33	NC	AT32	NC
AP34	VSS_IO	AR34	I2C_SDA	AT33	INT[7]
AP35	U0_RX	AR35	U0_TX	AT34	INT[14]
AP36	U1_RX	AR36	U0_CTS#	AT35	I2C_SCLK
AP37	U1_CTS#	AR37	U0_RTS#	AT36	VSS_IO
AP38	XS_IRQ[1]	AR38	XS_FIQ[1]	AT37	U1_RTS#
AP39	XS_IRQ[0]	AR39	XS_FIQ[0]	AT38	U0_RI#
AR1	P2_GNT#[6]	AT1	P2_HS_64EN#	AT39	XS_RESET#
AR2	P2_REQ#[7]	AT2	P2_PCIXCAP[1]	AU1	P2_ES
AR3	P2_REQ#[6]	AT3	P2_PCIXCAP[0]	AU2	VSS_IO
AR4	P2_GNT#[7]	AT4	VSS_IO	AU3	VSS_IO
AR5	VSS_IO	AT5	P1_RST#	AU4	P1_IDSEL
AR6	P1_AD[29]	AT6	P1_GNT#[1]	AU5	P1_AD[28]
AR7	P1_CLK_IN	AT7	P1_AD[30]	AU6	P1_HEALTHY#
AR8	P1_AD[23]	AT8	P1_AD[24]	AU7	P1_INTC#
AR9	P1_DEVSEL#	AT9	P1_IRDY#	AU8	P1_AD[25]
AR10	VSS_IO	AT10	P1_AD[18]	AU9	P1_AD[20]
AR11	P1_FRAME#	AT11	P1_PAR	AU10	P1_AD[19]
AR12	VSS_IO	AT12	P1_AD[15]	AU11	P1_AD[12]
AR13	P1_RSTDIR	AT13	P1_AD[9]	AU12	P1_AD[13]
AR14	VSS_IO	AT14	P1_AD[8]	AU13	P1_AD[6]
AR15	P1_AD[3]	AT15	P1_AD[4]	AU14	P1_CBE#[0]
AR16	VSS_IO	AT16	P1_REQ#[2]	AU15	P1_GNT#[5]
AR17	P1_GNT#[4]	AT17	P1_REQ#[5]	AU16	P1_AD[0]
AR18	VSS_IO	AT18	P1_CBE#[7]	AU17	P1_AD[63]
AR19	P1_AD[61]			AU18	P1_GNT#[3]

Ball	Signal Name	Ball	Signal Name	Ball	Signal Name
AU19	P1_CBE#[4]	AV20	P1_AD[51]	AW23	P1_AD[50]
AU20	P1_AD[56]	AV21	VSS_IO	AW24	P1_AD[45]
AU21	P1_AD[46]	AV22	P1_AD[41]	AW25	P1_AD[37]
AU22	P1_AD[47]	AV23	VSS_IO	AW26	PWRUP_P2_SWRS T
AU23	P1_AD[38]	AV24	P1_REQ#[6]	AW27	P1_PCIXCAP[1]
AU24	P1_AD[40]	AV25	VSS_IO	AW28	PWRUP_XS_SWRS T
AU25	P1_AD[34]	AV26	P1_PCIXCAP[0]	AW29	PWRUP_PBI_BSW P
AU26	P1_AD[35]	AV27	P1_AD[33]	AW30	P1_AD[36]
AU27	P1_ES	AV28	P1_AD[39]	AW31	SF_CLK
AU28	P1_AD[32]	AV29	VSS_IO	AW32	INT[9]
AU29	PWRUP_P2_PRIM	AV30	INT[0]	AW33	NC
AU30	TDI	AV31	INT[3]	AW34	PWRUP_P2_ARB
AU31	INT[2]	AV32	PWRUP_P1_BYP	AW35	NC
AU32	VSS_IO	AV33	INT[10]	AW36	INT[4]
AU33	INT[6]	AV34	INT[8]	AW37	U1_RI#
AU34	INT[13]	AV35	INT[12]		
AU35	INT[15]	AV36	U1_TX		
AU36	PWRUP_P2_BYP	AV37	VSS_IO		
AU37	VSS_IO	AV38	VSS_IO		
AU38	VSS_IO	AW3	P1_REQ#[1]		
AU39	U1_DCD#	AW4	P1_INTA#		
AV2	VSS_IO	AW5	P1_INTB#		
AV3	VSS_IO	AW6	P1_AD[21]		
AV4	P1_INTD#	AW7	P1_AD[31]		
AV5	P1_AD[27]	AW8	P1_AD[26]		
AV6	VSS_IO	AW9	P1_PME#		
AV7	P1_CBE#[1]	AW10	P1_PERR#		
AV8	P1_SERR#	AW11	P1_CBE#[3]		
AV9	VSS_IO	AW12	P1_AD[22]		
AV10	P1_AD[17]	AW13	P1_CBE#[2]		
AV11	VSS_IO	AW14	P1_AD[16]		
AV12	P1_M66EN	AW15	P1_ACK64#		
AV13	VSS_IO	AW16	P1_AD[10]		
AV14	P1_AD[1]	AW17	P1_AD[5]		
AV15	VSS_IO	AW18	P1_REQ#[3]		
AV16	P1_GNT#[2]	AW19	P1_CBE#[6]		
AV17	VSS_IO	AW20	P1_REQ64#		
AV18	P1_AD[60]	AW21	P1_AD[59]		
AV19	VSS_IO	AW22	P1_AD[55]		

Table 21. 1025-Lead HSBGA Package - Alphabetical Signal Listings

Signal Name	Ball	Signal Name	Ball	Signal Name	Ball
NC	AR29	E1_RCG[1]	L2	INT[15]	AU35
E0_ECMDT	A3	E1_RCG[2]	J3	MDC	C5
E0_EWRAP	E2	E1_RCG[3]	N4	MDIO	B5
E0_PCOL_RBCM	D1	E1_RCG[4]	M4	NC_J35	J35
E0_PCRS_SDET	D3	E1_RCG[5]	K5	NC_K34	K34
E0_PMA_CLK0	G5	E1_RCG[6]	P6	NC_L6	L6
E0_PMA_CLK1	C4	E1_RCG[7]	M5	NC_M33	M33
E0_PRBS_PASS	D5	E1_RCG[8]	P5	NC_N6	N6
E0_PRBSEN	C6	E1_RCG[9]	R6	P1_ACK64#	AW15
E0_RCG[0]	E5	E1_TCG[0]	J5	P1_AD[0]	AU16
E0_RCG[1]	E1	E1_TCG[1]	H4	P1_AD[1]	AV14
E0_RCG[2]	F5	E1_TCG[2]	J1	P1_AD[2]	AP15
E0_RCG[3]	C1	E1_TCG[3]	H2	P1_AD[3]	AR15
E0_RCG[4]	F1	E1_TCG[4]	H3	P1_AD[4]	AT15
E0_RCG[5]	F2	E1_TCG[5]	F3	P1_AD[5]	AW17
E0_RCG[6]	F4	E1_TCG[6]	K1	P1_AD[6]	AU13
E0_RCG[7]	H1	E1_TCG[7]	H5	P1_AD[7]	AP14
E0_RCG[8]	G1	E1_TCG[8]	J4	P1_AD[8]	AT14
E0_RCG[9]	G2	E1_TCG[9]	G4	P1_AD[9]	AT13
E0_TCG[0]	E4	NC	AW35	P1_AD[10]	AW16
E0_TCG[1]	B4	GTX_CLK	L4	P1_AD[11]	AP13
E0_TCG[2]	D6	I2C_SCLK	AT35	P1_AD[12]	AU11
E0_TCG[3]	A5	I2C_SDA	AR34	P1_AD[13]	AU12
E0_TCG[4]	E3	INT[0]	AV30	P1_AD[14]	AP12
E0_TCG[5]	A4	INT[1]	AR30	P1_AD[15]	AT12
E0_TCG[6]	F8	INT[2]	AU31	P1_AD[16]	AW14
E0_TCG[7]	D2	INT[3]	AV31	P1_AD[17]	AV10
E0_TCG[8]	D7	INT[4]	AW36	P1_AD[18]	AT10
E0_TCG[9]	B6	INT[5]	AP32	P1_AD[19]	AU10
E1_ECMDT	P4	INT[6]	AU33	P1_AD[20]	AU9
E1_EWRAP	K2	INT[7]	AT33	P1_AD[21]	AW6
E1_PCOL_RBCM	E7	INT[8]	AV34	P1_AD[22]	AW12
E1_PCRS_SDET	N3	INT[9]	AW32	P1_AD[23]	AR8
E1_PMA_CLK0	M3	INT[10]	AV33	P1_AD[24]	AT8
E1_PMA_CLK1	J2	INT[11]	AR32	P1_AD[25]	AU8
E1_PRBS_PASS	N5	INT[12]	AV35	P1_AD[26]	AW8
E1_PRBSEN	L5	INT[13]	AU34	P1_AD[27]	AV5
E1_RCG[0]	L3	INT[14]	AT34	P1_AD[28]	AU5

Signal Name	Ball	Signal Name	Ball	Signal Name	Ball
P1_AD[29]	AR6	P1_CBE#[4]	AU19	P1_REQ#[5]	AT17
P1_AD[30]	AT7	P1_CBE#[5]	AP19	P1_REQ#[6]	AV24
P1_AD[31]	AW7	P1_CBE#[6]	AW19	P1_REQ#[7]	AP24
P1_AD[32]	AU28	P1_CBE#[7]	AT18	P1_REQ64#	AW20
P1_AD[33]	AV27	P1_CLK_IN	AR7	P1_RST#	AT5
P1_AD[34]	AU25	P1_CLK_OUT	AP8	P1_RSTDIR	AR13
P1_AD[35]	AU26	P1_DEVSEL#	AR9	P1_SERR#	AV8
P1_AD[36]	AW30	P1_ENUM#	AP16	P1_STOP#	AP11
P1_AD[37]	AW25	P1_ES	AU27	P1_TRDY#	AP10
P1_AD[38]	AU23	P1_FRAME#	AR11	P2_ACK64#	AB1
P1_AD[39]	AV28	P1_GNT#[1]	AT6	P2_AD[0]	AE3
P1_AD[40]	AU24	P1_GNT#[2]	AV16	P2_AD[1]	AE2
P1_AD[41]	AV22	P1_GNT#[3]	AU18	P2_AD[2]	AE6
P1_AD[42]	AP23	P1_GNT#[4]	AR17	P2_AD[3]	AC4
P1_AD[43]	AR23	P1_GNT#[5]	AU15	P2_AD[4]	AD4
P1_AD[44]	AT23	P1_GNT#[6]	AT25	P2_AD[5]	AD1
P1_AD[45]	AW24	P1_GNT#[7]	AT24	P2_AD[6]	AD3
P1_AD[46]	AU21	P1_HEALTHY#	AU6	P2_AD[7]	AD6
P1_AD[47]	AU22	P1_HS_64EN#	AT27	P2_AD[8]	AC5
P1_AD[48]	AP22	P1_IDSEL	AU4	P2_AD[9]	AB4
P1_AD[49]	AT22	P1_INTA#	AW4	P2_AD[10]	AC1
P1_AD[50]	AW23	P1_INTB#	AW5	P2_AD[11]	AC6
P1_AD[51]	AV20	P1_INTC#	AU7	P2_AD[12]	AB2
P1_AD[52]	AP21	P1_INTD#	AV4	P2_AD[13]	AB3
P1_AD[53]	AR21	P1_IRDY#	AT9	P2_AD[14]	AB6
P1_AD[54]	AT21	P1_LED#	AT26	P2_AD[15]	Y5
P1_AD[55]	AW22	P1_M66EN	AV12	P2_AD[16]	AA1
P1_AD[56]	AU20	P1_PAR	AT11	P2_AD[17]	AA2
P1_AD[57]	AP20	P1_PAR64	AP18	P2_AD[18]	W4
P1_AD[58]	AT20	P1_PCIXCAP[0]	AV26	P2_AD[19]	Y3
P1_AD[59]	AW21	P1_PCIXCAP[1]	AW27	P2_AD[20]	W3
P1_AD[60]	AV18	P1_PERR#	AW10	P2_AD[21]	U1
P1_AD[61]	AR19	P1_PLL_AVCC	AP9	P2_AD[22]	W1
P1_AD[62]	AT19	P1_PLL_AVSS	AP7	P2_AD[23]	V5
P1_AD[63]	AU17	P1_PME#	AW9	P2_AD[24]	T4
P1_CBE#[0]	AU14	P1_REQ#[1]	AW3	P2_AD[25]	V3
P1_CBE#[1]	AV7	P1_REQ#[2]	AT16	P2_AD[26]	R1
P1_CBE#[2]	AW13	P1_REQ#[3]	AW18	P2_AD[27]	T2
P1_CBE#[3]	AW11	P1_REQ#[4]	AP17	P2_AD[28]	T3

Signal Name	Ball	Signal Name	Ball	Signal Name	Ball
P2_AD[29]	V4	P2_CBE#[4]	AG1	P2_REQ#[5]	AF4
P2_AD[30]	R4	P2_CBE#[5]	AJ6	P2_REQ#[6]	AR3
P2_AD[31]	P1	P2_CBE#[6]	AE1	P2_REQ#[7]	AR2
P2_AD[32]	AP4	P2_CBE#[7]	AD5	P2_REQ64#	AK3
P2_AD[33]	AP5	P2_CLK_IN	T5	P2_RST#	P2
P2_AD[34]	AP1	P2_CLK_OUT	U6	P2_RSTDIR	AA5
P2_AD[35]	AN3	P2_DEVSEL#	W6	P2_SERR#	W2
P2_AD[36]	AP6	P2_ENUM#	AF6	P2_STOP#	AA6
P2_AD[37]	AN1	P2_ES	AU1	P2_TRDY#	Y6
P2_AD[38]	AP3	P2_FRAME#	Y4	PBI_AD[0]	K36
P2_AD[39]	AM5	P2_GNT#[1]	M1	PBI_AD[1]	P35
P2_AD[40]	AM4	P2_GNT#[2]	AF3	PBI_AD[2]	L34
P2_AD[41]	AN2	P2_GNT#[3]	AG3	PBI_AD[3]	M35
P2_AD[42]	AN6	P2_GNT#[4]	AF5	PBI_AD[4]	D33
P2_AD[43]	AL4	P2_GNT#[5]	AG2	PBI_AD[5]	H37
P2_AD[44]	AL3	P2_GNT#[6]	AR1	PBI_AD[6]	N34
P2_AD[45]	AM1	P2_GNT#[7]	AR4	PBI_AD[7]	P34
P2_AD[46]	AL1	P2_HEALTHY#	R2	PBI_AD[8]	J37
P2_AD[47]	AM3	P2_HS_64EN#	AT1	PBI_AD[9]	H35
P2_AD[48]	AM6	P2_IDSEL	R3	PBI_AD[10]	H36
P2_AD[49]	AK5	P2_INTA#	P3	PBI_AD[11]	H39
P2_AD[50]	AK1	P2_INTB#	N1	PBI_AD[12]	H38
P2_AD[51]	AL2	P2_INTC#	U3	PBI_AD[13]	G39
P2_AD[52]	AL6	P2_INTD#	L1	PBI_AD[14]	G36
P2_AD[53]	AJ4	P2_IRDY#	U4	PBI_AD[15]	F36
P2_AD[54]	AK4	P2_LED#	AN4	PBI_AD[16]	G38
P2_AD[55]	AJ1	P2_M66EN	AD2	PBI_AD[17]	F39
P2_AD[56]	AJ3	P2_PAR	AA4	PBI_AD[18]	E37
P2_AD[57]	AK6	P2_PAR64	AH6	PBI_AD[19]	D39
P2_AD[58]	AH5	P2_PCIXCAP[0]	AT3	PBI_AD[20]	E38
P2_AD[59]	AH1	P2_PCIXCAP[1]	AT2	PBI_AD[21]	E34
P2_AD[60]	AJ2	P2_PERR#	AA3	PBI_AD[22]	E36
P2_AD[61]	AG4	P2_PLL_AVCC	V6	PBI_AD[23]	D37
P2_AD[62]	AH4	P2_PLL_AVSS	T6	PBI_AD[24]	C39
P2_AD[63]	AH3	P2_PME#	T1	PBI_AD[25]	D38
P2_CBE#[0]	AC3	P2_REQ#[1]	M2	PBI_AD[26]	E33
P2_CBE#[1]	V2	P2_REQ#[2]	AG6	PBI_AD[27]	C36
P2_CBE#[2]	Y1	P2_REQ#[3]	AE4	PBI_AD[28]	D35
P2_CBE#[3]	V1	P2_REQ#[4]	AF1	PBI_AD[29]	B36

Signal Name	Ball	Signal Name	Ball	Signal Name	Ball
PBI_AD[30]	F32	SD_BA[0]	A17	SD_DQ[17]	F26
PBI_AD[31]	C35	SD_BA[1]	A19	SD_DQ[18]	C25
PBI_CS#[0]	F35	SD_CAS#	A13	SD_DQ[19]	E23
PBI_CS#[1]	F37	SD_CKFBI	A34	SD_DQ[20]	C28
PBI_CS#[2]	G35	SD_CKFBO	B35	SD_DQ[21]	C27
PBI_CS#[3]	D34	SD_CLK#[0]	B21	SD_DQ[22]	E24
PBI_LE	G32	SD_CLK#[1]	B23	SD_DQ[23]	F23
PBI_OE#	J36	SD_CLK#[2]	B24	SD_DQ[24]	D24
PBI_RDY#	K35	SD_CLK#[3]	B18	SD_DQ[25]	C23
PBI_RW	F38	SD_CLK[0]	A21	SD_DQ[26]	C21
PWRUP_P1_ARB	AP26	SD_CLK[1]	A23	SD_DQ[27]	D19
PWRUP_P1_BYP	AV32	SD_CLK[2]	A24	SD_DQ[28]	C22
PWRUP_P1_PRIM	AR25	SD_CLK[3]	A18	SD_DQ[29]	D22
PWRUP_P1_SWRS T	AR26	SD_CLKEN	B9	SD_DQ[30]	F19
PWRUP_P2_ARB	AW34	SD_CS#[0]	A14	SD_DQ[31]	E18
PWRUP_P2_BYP	AU36	SD_CS#[1]	B14	SD_DQ[32]	C17
PWRUP_P2_PRIM	AU29	SD_CS#[2]	A15	SD_DQ[33]	D16
PWRUP_P2_SWRS T	AW26	SD_CS#[3]	B15	SD_DQ[34]	E14
PWRUP_PBI_BSW P	AW29	SD_CS#[4]	A35	SD_DQ[35]	C12
PWRUP_TRANS	AP27	SD_CS#[5]	B33	SD_DQ[36]	F17
PWRUP_XS_SWRS T	AW28	SD_CS#[6]	A37	SD_DQ[37]	C16
REF125M	K4	SD_CS#[7]	A36	SD_DQ[38]	C13
SD_A[0]	A20	SD_DQ[0]	D31	SD_DQ[39]	D13
SD_A[1]	A22	SD_DQ[1]	A31	SD_DQ[40]	F16
SD_A[2]	A25	SD_DQ[2]	C29	SD_DQ[41]	F14
SD_A[3]	B26	SD_DQ[3]	E28	SD_DQ[42]	F13
SD_A[4]	A26	SD_DQ[4]	C34	SD_DQ[43]	B12
SD_A[5]	A27	SD_DQ[5]	E31	SD_DQ[44]	E16
SD_A[6]	B27	SD_DQ[6]	C30	SD_DQ[45]	E15
SD_A[7]	B29	SD_DQ[7]	E30	SD_DQ[46]	A12
SD_A[8]	A28	SD_DQ[8]	A33	SD_DQ[47]	E12
SD_A[9]	A29	SD_DQ[9]	D30	SD_DQ[48]	C11
SD_A[10]	B20	SD_DQ[10]	D25	SD_DQ[49]	C10
SD_A[11]	B30	SD_DQ[11]	C24	SD_DQ[50]	D11
SD_A[12]	A30	SD_DQ[12]	F29	SD_DQ[51]	D12
SD_A[13]	B32	SD_DQ[13]	D28	SD_DQ[52]	D8
		SD_DQ[14]	E26	SD_DQ[53]	C9
		SD_DQ[15]	E25	SD_DQ[54]	D9
		SD_DQ[16]	E27	SD_DQ[55]	D10

Signal Name	Ball	Signal Name	Ball	Signal Name	Ball
SD_DQ[56]	B11	SD_RAS#	B17	VCC_CORE	AC18
SD_DQ[57]	A10	SD_VREF	A8	VCC_CORE	AC20
SD_DQ[58]	C8	SD_WE#	A16	VCC_CORE	AC22
SD_DQ[59]	E9	SF_CLK	AW31	VCC_CORE	AC24
SD_DQ[60]	A11	SF_RST#	AP25	VCC_CORE	AD15
SD_DQ[61]	F12	NC	AW33	VCC_CORE	AD17
SD_DQ[62]	B8	TCK	AT29	VCC_CORE	AD19
SD_DQ[63]	A6	TDI	AU30	VCC_CORE	AD21
SD_DQS[0]	E29	TDO	AP28	VCC_CORE	AD23
SD_DQS[1]	F28	NC	AR31	VCC_CORE	AD25
SD_DQS[2]	C26	NC	AT32	VCC_CORE	AE16
SD_DQS[3]	F20	NC	AT30	VCC_CORE	AE18
SD_DQS[4]	C15	NC	AR33	VCC_CORE	AE20
SD_DQS[5]	E13	NC	AT31	VCC_CORE	AE22
SD_DQS[6]	A7	TMS	AT28	VCC_CORE	AE24
SD_DQS[7]	A9	TRST#	AR27	VCC_CORE	AK08
SD_DQS[8]	C20	U0_CTS#	AR36	VCC_CORE	AK32
SD_DQS[9]	C31	U0_DCD#	AM34	VCC_CORE	AL32
SD_DQS[10]	D27	U0_DSR#	AN36	VCC_CORE	AL8
SD_DQS[11]	F25	U0_DTR#	AM35	VCC_CORE	AM10
SD_DQS[12]	D21	U0_RI#	AT38	VCC_CORE	AM30
SD_DQS[13]	D15	U0_RTS#	AR37	VCC_CORE	AM31
SD_DQS[14]	C14	U0_RX	AP35	VCC_CORE	AM32
SD_DQS[15]	C7	U0_TX	AR35	VCC_CORE	AM8
SD_DQS[16]	E10	U1_CTS#	AP37	VCC_CORE	AM9
SD_DQS[17]	E19	U1_DCD#	AU39	VCC_CORE	AN29
SD_ECC[0]	F22	U1_DSR#	AN34	VCC_CORE	F7
SD_ECC[1]	E20	U1_DTR#	AL34	VCC_CORE	G7
SD_ECC[2]	C19	U1_RI#	AW37	VCC_CORE	G8
SD_ECC[3]	C18	U1_RTS#	AT37	VCC_CORE	H10
SD_ECC[4]	E22	U1_RX	AP36	VCC_CORE	H30
SD_ECC[5]	E21	U1_TX	AV36	VCC_CORE	H31
SD_ECC[6]	D18	VCC_CORE	AA16	VCC_CORE	H32
SD_ECC[7]	E17	VCC_CORE	AA24	VCC_CORE	H8
SD_I2C_CLK	C32	VCC_CORE	AB15	VCC_CORE	H9
SD_I2C_SDA	A32	VCC_CORE	AB17	VCC_CORE	J32
SD_PLL_AVCC	G30	VCC_CORE	AB23	VCC_CORE	J7
SD_PLL_AVSS	D32	VCC_CORE	AB25	VCC_CORE	J8
SD_PWRDELAY	C33	VCC_CORE	AC16	VCC_CORE	K32

Signal Name	Ball	Signal Name	Ball	Signal Name	Ball
VCC_CORE	K7	VCC_PC	AL7	VCC_PC	P7
VCC_CORE	K8	VCC_PC	AM33	VCC_PC	R7
VCC_CORE	L7	VCC_PC	AM7	VCC_PC	T7
VCC_CORE	R16	VCC_PC	AN10	VCC_PC	U7
VCC_CORE	R18	VCC_PC	AN11	VCC_PC	V7
VCC_CORE	R20	VCC_PC	AN12	VCC_PC	W7
VCC_CORE	R22	VCC_PC	AN13	VCC_PC	Y7
VCC_CORE	R24	VCC_PC	AN14	VCC_SD	F10
VCC_CORE	T15	VCC_PC	AN15	VCC_SD	F11
VCC_CORE	T17	VCC_PC	AN16	VCC_SD	F31
VCC_CORE	T19	VCC_PC	AN17	VCC_SD	F9
VCC_CORE	T21	VCC_PC	AN18	VCC_SD	G10
VCC_CORE	T23	VCC_PC	AN19	VCC_SD	G11
VCC_CORE	T25	VCC_PC	AN20	VCC_SD	G12
VCC_CORE	U16	VCC_PC	AN21	VCC_SD	G13
VCC_CORE	U18	VCC_PC	AN22	VCC_SD	G14
VCC_CORE	U20	VCC_PC	AN23	VCC_SD	G15
VCC_CORE	U22	VCC_PC	AN24	VCC_SD	G16
VCC_CORE	U24	VCC_PC	AN25	VCC_SD	G17
VCC_CORE	V15	VCC_PC	AN26	VCC_SD	G18
VCC_CORE	V17	VCC_PC	AN27	VCC_SD	G19
VCC_CORE	V23	VCC_PC	AN28	VCC_SD	G20
VCC_CORE	V25	VCC_PC	AN29	VCC_SD	G21
VCC_CORE	W16	VCC_PC	AN30	VCC_SD	G22
VCC_CORE	W24	VCC_PC	AN30	VCC_SD	G23
VCC_CORE	Y15	VCC_PC	AN31	VCC_SD	G24
VCC_CORE	Y17	VCC_PC	AN31	VCC_SD	G25
VCC_CORE	Y23	VCC_PC	AN32	VCC_SD	G26
VCC_CORE	Y25	VCC_PC	AN33	VCC_SD	G27
VCC_PC	AA7	VCC_PC	AN8	VCC_SD	G28
VCC_PC	AB7	VCC_PC	AN9	VCC_SD	G29
VCC_PC	AC7	VCC_PC	F6	VCC_SD	G31
VCC_PC	AD7	VCC_PC	G6	VCC_SD	G9
VCC_PC	AE7	VCC_PC	H6	VCC_XS	AA33
VCC_PC	AF7	VCC_PC	H7	VCC_XS	AB33
VCC_PC	AG7	VCC_PC	J6	VCC_XS	AC33
VCC_PC	AH7	VCC_PC	K6	VCC_XS	AD33
VCC_PC	AJ7	VCC_PC	M7	VCC_XS	AE33
VCC_PC	AK7	VCC_PC	N7	VCC_XS	AF33

Signal Name	Ball	Signal Name	Ball	Signal Name	Ball
VCC_XS	AG33	VSS_CORE	AC17	VSS_CORE	V24
VCC_XS	AH33	VSS_CORE	AC19	VSS_CORE	W15
VCC_XS	AJ33	VSS_CORE	AC21	VSS_CORE	W17
VCC_XS	AK33	VSS_CORE	AC23	VSS_CORE	W18
VCC_XS	AL33	VSS_CORE	AC25	VSS_CORE	W19
VCC_XS	F33	VSS_CORE	AD16	VSS_CORE	W20
VCC_XS	F34	VSS_CORE	AD18	VSS_CORE	W21
VCC_XS	G33	VSS_CORE	AD20	VSS_CORE	W22
VCC_XS	G34	VSS_CORE	AD22	VSS_CORE	W23
VCC_XS	H33	VSS_CORE	AD24	VSS_CORE	W25
VCC_XS	H34	VSS_CORE	AE15	VSS_CORE	Y16
VCC_XS	J33	VSS_CORE	AE17	VSS_CORE	Y18
VCC_XS	J34	VSS_CORE	AE19	VSS_CORE	Y19
VCC_XS	K33	VSS_CORE	AE21	VSS_CORE	Y20
VCC_XS	N33	VSS_CORE	AE23	VSS_CORE	Y21
VCC_XS	P33	VSS_CORE	AE25	VSS_CORE	Y22
VCC_XS	R33	VSS_CORE	R15	VSS_CORE	Y24
VCC_XS	T33	VSS_CORE	R17	VSS_IO	B2
VCC_XS	U33	VSS_CORE	R19	VSS_IO	B3
VCC_XS	V33	VSS_CORE	R21	VSS_IO	B7
VCC_XS	W33	VSS_CORE	R23	VSS_IO	B10
VCC_XS	Y33	VSS_CORE	R25	VSS_IO	B13
VSS_CORE	AA15	VSS_CORE	T16	VSS_IO	B16
VSS_CORE	AA17	VSS_CORE	T18	VSS_IO	B19
VSS_CORE	AA18	VSS_CORE	T20	VSS_IO	B22
VSS_CORE	AA19	VSS_CORE	T22	VSS_IO	B25
VSS_CORE	AA20	VSS_CORE	T24	VSS_IO	B28
VSS_CORE	AA21	VSS_CORE	U15	VSS_IO	B31
VSS_CORE	AA22	VSS_CORE	U17	VSS_IO	B34
VSS_CORE	AA23	VSS_CORE	U19	VSS_IO	B37
VSS_CORE	AA25	VSS_CORE	U21	VSS_IO	B38
VSS_CORE	AB16	VSS_CORE	U23	VSS_IO	AA35
VSS_CORE	AB18	VSS_CORE	U25	VSS_IO	AB38
VSS_CORE	AB19	VSS_CORE	V16	VSS_IO	AB5
VSS_CORE	AB20	VSS_CORE	V18	VSS_IO	AC2
VSS_CORE	AB21	VSS_CORE	V19	VSS_IO	AC35
VSS_CORE	AB22	VSS_CORE	V20	VSS_IO	AD38
VSS_CORE	AB24	VSS_CORE	V21	VSS_IO	AE35
VSS_CORE	AC15	VSS_CORE	V22	VSS_IO	AE5

Signal Name	Ball	Signal Name	Ball	Signal Name	Ball
VSS_IO	AF2	VSS_IO	AV15	VSS_IO	J39
VSS_IO	AF38	VSS_IO	AV17	VSS_IO	K3
VSS_IO	AG35	VSS_IO	AV19	VSS_IO	L35
VSS_IO	AG5	VSS_IO	AV2	VSS_IO	M38
VSS_IO	AH2	VSS_IO	AV21	VSS_IO	M6
VSS_IO	AH38	VSS_IO	AV23	VSS_IO	N2
VSS_IO	AJ35	VSS_IO	AV25	VSS_IO	N35
VSS_IO	AJ5	VSS_IO	AV29	VSS_IO	P38
VSS_IO	AK2	VSS_IO	AV3	VSS_IO	R35
VSS_IO	AK38	VSS_IO	AV37	VSS_IO	R5
VSS_IO	AL35	VSS_IO	AV38	VSS_IO	T38
VSS_IO	AL5	VSS_IO	AV6	VSS_IO	U2
VSS_IO	AM2	VSS_IO	AV9	VSS_IO	U35
VSS_IO	AM38	VSS_IO	C2	VSS_IO	U5
VSS_IO	AN35	VSS_IO	C3	VSS_IO	V38
VSS_IO	AN5	VSS_IO	C37	VSS_IO	W35
VSS_IO	AN7	VSS_IO	C38	VSS_IO	W5
VSS_IO	AP2	VSS_IO	D14	VSS_IO	Y2
VSS_IO	AP33	VSS_IO	D17	VSS_IO	Y38
VSS_IO	AP34	VSS_IO	D20	XS_A[0]	AH34
VSS_IO	AR10	VSS_IO	D23	XS_A[1]	AG38
VSS_IO	AR12	VSS_IO	D26	XS_A[2]	AG39
VSS_IO	AR14	VSS_IO	D29	XS_A[3]	AG37
VSS_IO	AR16	VSS_IO	D36	XS_A[4]	AF36
VSS_IO	AR18	VSS_IO	D4	XS_A[5]	AJ34
VSS_IO	AR20	VSS_IO	E11	XS_A[6]	AH37
VSS_IO	AR22	VSS_IO	E32	XS_A[7]	AH39
VSS_IO	AR24	VSS_IO	E35	XS_A[8]	AF37
VSS_IO	AR28	VSS_IO	E39	XS_A[9]	AK34
VSS_IO	AR5	VSS_IO	E6	XS_A[10]	AJ36
VSS_IO	AT36	VSS_IO	E8	XS_A[11]	AH35
VSS_IO	AT4	VSS_IO	F15	XS_A[12]	AG36
VSS_IO	AU2	VSS_IO	F18	XS_A[13]	AF35
VSS_IO	AU3	VSS_IO	F21	XS_A[14]	AH36
VSS_IO	AU32	VSS_IO	F24	XS_A[15]	AJ39
VSS_IO	AU37	VSS_IO	F27	XS_ABORT	AF34
VSS_IO	AU38	VSS_IO	F30	XS_BE[0]	AC36
VSS_IO	AV11	VSS_IO	G3	XS_BE[1]	AD34
VSS_IO	AV13	VSS_IO	G37	XS_BE[2]	AC37

Signal Name	Ball	Signal Name	Ball	Signal Name	Ball
XS_BE[3]	AC39	XS_DQ[32]	W39	XS_ECC[5]	AB36
XS_BE[4]	AD39	XS_DQ[33]	V37	XS_ECC[6]	AB39
XS_BE[5]	AC38	XS_DQ[34]	V36	XS_ECC[7]	AB37
XS_BE[6]	AE34	XS_DQ[35]	W36	XS_FIQ[0]	AR39
XS_BE[7]	AE36	XS_DQ[36]	V39	XS_FIQ[1]	AR38
XS_CLK	K38	XS_DQ[37]	W34	XS_HLDA[0]	AG34
XS_CWF	AE37	XS_DQ[38]	V35	XS_HLDA[1]	AE38
XS_DQ[0]	Y35	XS_DQ[39]	U38	XS_HOLD[0]	AE39
XS_DQ[1]	Y37	XS_DQ[40]	R38	XS_HOLD[1]	AF39
XS_DQ[2]	Y36	XS_DQ[41]	T34	XS_IRQ[0]	AP39
XS_DQ[3]	W38	XS_DQ[42]	T36	XS_IRQ[1]	AP38
XS_DQ[4]	Y39	XS_DQ[43]	R36	XS_LEN[0]	AD36
XS_DQ[5]	AA34	XS_DQ[44]	R39	XS_LEN[1]	AD37
XS_DQ[6]	Y34	XS_DQ[45]	R34	XS_LEN[2]	AD35
XS_DQ[7]	W37	XS_DQ[46]	R37	XS_PLL_AVCC	L33
XS_DQ[8]	V34	XS_DQ[47]	P39	XS_PLL_AVSS	M34
XS_DQ[9]	U37	XS_DQ[48]	J38	XS_RESET#	AT39
XS_DQ[10]	T35	XS_DQ[49]	K37		
XS_DQ[11]	U36	XS_DQ[50]	L36		
XS_DQ[12]	U39	XS_DQ[51]	K39		
XS_DQ[13]	U34	XS_DQ[52]	L37		
XS_DQ[14]	T37	XS_DQ[53]	L39		
XS_DQ[15]	T39	XS_DQ[54]	M37		
XS_DQ[16]	N38	XS_DQ[55]	M36		
XS_DQ[17]	P36	XS_DQ[56]	AJ37		
XS_DQ[18]	N37	XS_DQ[57]	AK36		
XS_DQ[19]	N36	XS_DQ[58]	AL36		
XS_DQ[20]	L38	XS_DQ[59]	AJ38		
XS_DQ[21]	P37	XS_DQ[60]	AK35		
XS_DQ[22]	N39	XS_DQ[61]	AK37		
XS_DQ[23]	M39	XS_DQ[62]	AK39		
XS_DQ[24]	AN38	XS_DQ[63]	AM36		
XS_DQ[25]	AN37	XS_DVALID[0]	AA36		
XS_DQ[26]	AN39	XS_DVALID[1]	AB34		
XS_DQ[27]	AL38	XS_ECC[0]	AA38		
XS_DQ[28]	AM39	XS_ECC[1]	AA39		
XS_DQ[29]	AL39	XS_ECC[2]	AA37		
XS_DQ[30]	AL37	XS_ECC[3]	AB35		
XS_DQ[31]	AM37	XS_ECC[4]	AC34		

3.2 Package Thermal Specifications

The device is specified for operation when T_C (case temperature) is within the range of 0°C to 105°C, depending on operating conditions. Case temperature may be measured in any environment to determine whether the processor is within specified operating range. Case temperature is best measured at the center of the top surface, opposite the ballpad.

3.2.1 Thermal Characteristics

Table 22 summarizes the thermal simulation data for the GW80314.

The thermal performance of the GW80314 package is represented by the following parameters:

1. θ_{JA} , Thermal resistance from junction to ambient
 $\theta_{JA} = (T_J - T_A) / P$

Where,

T_J is the junction temperature
 T_A is the ambient temperature
 P is the power dissipation

θ_{JA} represents the resistance to the heat from the chip to ambient air. It is an index of heat dissipation capability. The lower value for θ_{JA} means better thermal performance.

2. ψ_{JT} , Thermal characterization parameter from junction-to-top center
 $\psi_{JT} = (T_J - T_T) / P$

Where,

T_T is the temperature of the top-center of the package
 ψ_{JT} is used to estimate junction temperature by measuring T_T in an actual environment

3. θ_{JC} , Thermal resistance from junction to case
 $\theta_{JC} = (T_J - T_C) / P$

Where,

T_C is the case temperature

θ_{JC} is a measure of package internal thermal resistance from chip to package exterior.

The value is dependent upon package material and package geometry.

θ_{JA} , θ_{JC} , and ψ_{JT} simulations are carried out to show the thermal performance of the GW80314.

Table 22. Thermal Simulation Data for the Intel® GW80314 I/O Companion Chip

Package Conditions			
Package Type	HSBGA		
Ball Count	1025		
Package Size (mm)	40x40		
Mold Thickness (mm)	1.17		
Pitch (mm)	1		
Ball Matrix (mm)	39x39		
Ball Row Depth	7x7		
Thermal Ball Matrix	11x11		
Vias	144		
Pad Size (mm)	12.5x12.5		
Die Size (mm)	11.62x11.62		
Substrate Layer	4		
Substrate Thickness (mm)	0.56		
PCB Conditions (JEDEC JESD51-9)			
PCB Layer	4		
PCB Dimensions (mm)	127.0x139.5		
PCB Thickness (mm)	1.6		
Environment Conditions			
Maximum Junction Temperature (C)	125		
Ambient Temperature (C)	70		
Power Dissipation (W)	2.4 Typical 4.2 Max		
Required Theta ja (C/W)	12		
Thermal Data			
Property Vair(m/s)	Theta ja (C/W)	Psi jt (C/W)	Theta jc (C/W)
0.00	10.8	1.8	1.9
1.00	9.6	1.8	1.9
2.00	8.3	1.8	1.9
Heat Flow Path			
Heat Dissipated from PCB (%)	66.1		
(%)	15.9		
Heat Dissipated from Others (%)	18.0		

3.2.2 Ambient Temperature

Ambient temperature, T_A , is the temperature of the ambient air surrounding the package. In a system environment, ambient temperature is the temperature of the air upstream from the package.

3.2.3 Case Temperature

When measuring case temperature, T_C , attention to detail is required to ensure accuracy. When a thermocouple is used, calibrate is before taking measurements. Errors may result when the measured surface temperature is affected by the surrounding ambient air temperature. Such errors may be due to a poor thermal contact between thermocouple junction and the surface, heat loss by radiation, or conduction through thermocouple leads.

To minimize measurement errors:

- Use a 35 gauge K-type thermocouple or equivalent.
- Attach the thermocouple bead or junction to the package top surface at a location corresponding to the center of the die. The center of the die gives a more accurate measurement and less variation as the boundary condition changes.
- Attach the thermocouple bead at a 0° angle with respect to the package when no heatsink is attached.

3.2.4 Thermal Resistance

The thermal resistance value for the case-to-ambient, θ_{CA} , is used as a measure of the cooling solution's thermal performance.

3.3 Socket Information

Table 23 and Table 24 provide vendor details for socket-headers and burn-in sockets for the GW80314. This is neither an endorsement nor a warranty of the performance of any of the listed products and/or companies.

3.3.1 Socket-Header Vendor

Table 23. Socket-Header Vendor

Company	Factory Representative	Phone/Fax #	Part #	
			BGA 544-Pin Header	BGA 544-Pin Socket Carrier
TBD	TBD	TBD	TBD	TBD

3.3.2 Burn-in Socket Vendor

Table 24. Burn-in Socket Vendor

Company	Factory Representative	Phone #	Burn-in Socket Part #
TBD	TBD	TBD	TBD

3.3.3 Shipping Tray Vendor

Table 25. Shipping Tray Vendor

Company	Factory Representative	Phone #	Shipping Tray Part #
TBD	TBD	TBD	TBD

3.3.4 Logic Analyzer Interposer Vendor

Table 26. Logic Analyzer Interposer Vendor

Company	Factory Representative	Phone/Fax #	Part #
TBD	TBD	TBD	TBD

3.3.5 JTAG Emulator Vendor

Table 27. JTAG Emulator Vendor

Company	Part #
TBD	TBD
TBD	TBD

4.0 Electrical Specifications

4.1 Absolute Maximum Ratings

Table 28. Maximum Temperature and Voltage Ratings

Parameter	Maximum Rating
Storage Temperature T_{STG}	-40°C to +125°C
Case Temperature Under Bias T_C	0°C to + 90°C
Supply Voltage V_{CC33} wrt. V_{SS}	-0.5 V to +4.1 V (3.3 VDC)
Supply Voltage V_{CC25} wrt. V_{SS}	-0.5 V to +3.6 V (2.5 VDC)
Supply Voltage V_{CC12} wrt. V_{SS}	-0.5 V to +2.0 V (1.2 VDC)

WARNING: Stressing the device beyond the “Absolute Maximum Ratings” may cause permanent damage. These are stress ratings only. Operation beyond the “Operating Conditions” is not recommended and extended exposure beyond the “Operating Conditions” may affect device reliability.

Table 29. Operating Conditions

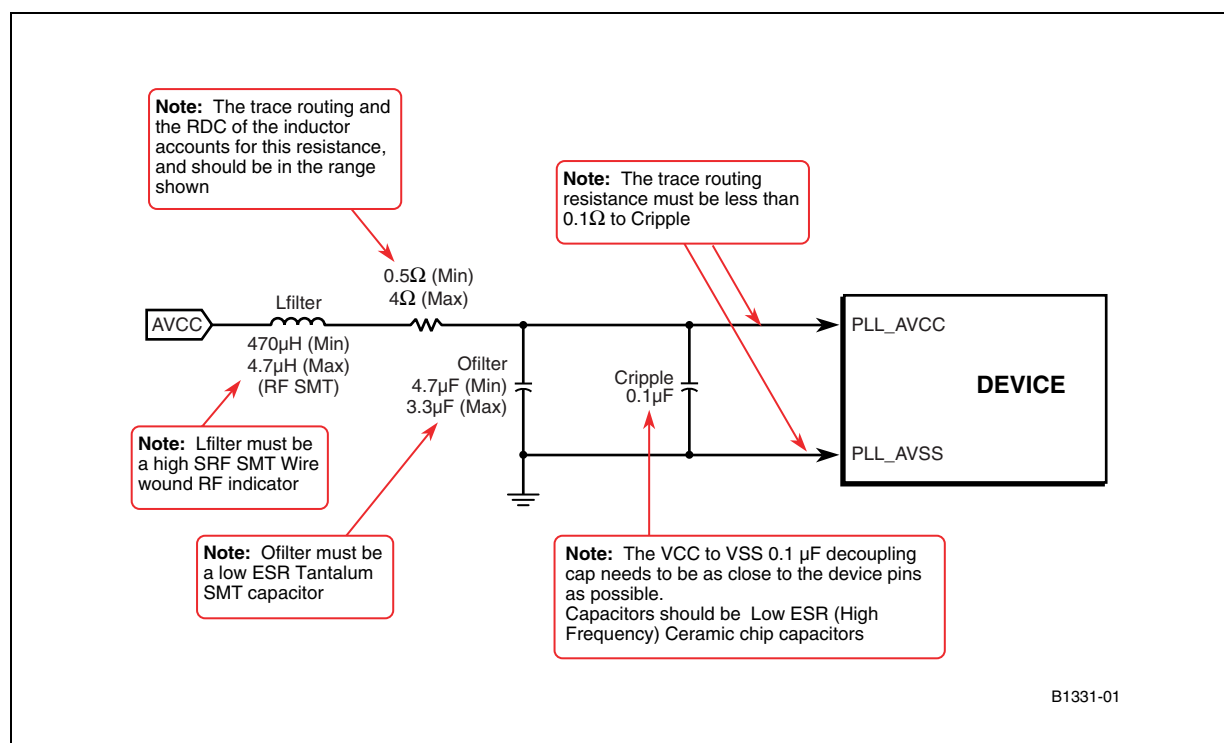
Symbol	Parameter	Min	Max	Units	Notes
V_{CC33}	3.3V Supply Voltage	3.0	3.6	V	
V_{CC25}	2.5V Supply Voltage	2.3	2.7	V	
V_{CC12}	1.2V Supply Voltage	1.08	1.32	V	
V_{PLL}	PLL Analog Supply Voltage	3.0	3.6	V	
I_{PLL}	PLL Analog Supply Current	-	10	mA	
T_A	Ambient Temperature	0	70	°C	

4.2 PLL Supply Pin Requirements

Package balls of the supply pins for the four Phase Lock Loops (PLLs) used on the GW80314 should be isolated and decoupled externally in order to provide the cleanest possible supply environment. The following pins are used as PLL supplies in the GW80314: XS_PLL_AVCC, SD_PLL_AVCC, P1_PLL_AVCC, and P2_PLL_AVCC. The recommended decoupling network for these pins is shown in Figure 5.

In order to minimize the transient IR drops across the leads from the isolation network and the PLL supply device pins, the trace routes must be kept short. It is preferred that the Cripple capacitor used in Figure 5 be placed as close to the device pins as possible, on the backside of the board underneath the device, if possible.

Figure 5. Intel® GW80314 I/O Companion Chip PLL Supply Decoupling Network



4.3 Targeted DC Specifications

Table 30. DC Characteristics

Symbol	Parameter	Minimum	Maximum	Units	Notes
V_{IL1}	SDRAM Input Low Voltage	-0.3	$V_{REF} - 0.12$	V	-
V_{IH1}	SDRAM Input High Voltage	$V_{REF} + 0.12$	$V_{CC25} + 0.3$	V	-
V_{IL2}	Misc Input Low Voltage	-0.3	0.8	V	1
V_{IH2}	Misc Input High Voltage	2.0	$V_{CC33} + 0.5$	V	1
V_{IL3}	GigE Input Low Voltage	-0.3	0.8	V	
V_{IH3}	GigE Input High Voltage	2.0	$V_{CC33} + 0.5$	V	4
V_{IL4}	PCI-X Input Low Voltage	-0.5	$0.35 \cdot V_{CC33}$	V	2
V_{IH4}	PCI-X/PCI Input High Voltage	$0.5 \cdot V_{CC33}$	$V_{CC33} + 0.5$	V	2
V_{IL5}	PCI Input Low Voltage	-0.5	$0.3 \cdot V_{CC33}$	V	2
V_{OL1}	Misc Output Low Voltage	-	0.4	V	$I_{OL} = 6\text{mA}$, 1, 5
V_{OH1}	Misc Output High Voltage	$V_{CC33min} - 0.5$	-	V	$I_{OL} = -6\text{mA}$, 1, 5
V_{OL2}	SDRAM Output Low Voltage	-	0.54	V	$I_{OL} = 7.6\text{mA}$
V_{OH2}	SDRAM Output High Voltage	$V_{CC25} - 0.54$	-	V	$I_{OL} = -7.6\text{mA}$
V_{OL3}	XScale Output Low Voltage	-	0.4	V	$I_{OL} = 8\text{mA}$, 5
V_{OH3}	XScale Output High Voltage	$V_{CC33min} - 0.5$	-		$I_{OL} = -8\text{mA}$, 4, 5
V_{OL4}	PCI-X Output Low Voltage	-	$0.1 \cdot V_{CC33}$	V	$I_{OL} = 1500\mu\text{A}$, 2
V_{OH4}	PCI-X Output High Voltage	$0.9 \cdot V_{CC33}$	-	V	$I_{OL} = -500\mu\text{A}$, 2
V_{OL5}	GigE Output Low Voltage	-	0.4	V	$I_{OL} = 12\text{mA}$, 5
V_{OH5}	GigE Output High Voltage	$V_{CC33min} - 0.5$	-	V	$I_{OL} = -12\text{mA}$, 4, 5
C_{IN}	Input Pin Capacitance	-	8	pF	2, 3
C_{CLK}	Clock Pin Capacitance	5	8	pF	2, 3
L_{PIN}	Ball Inductance	-	22	nH	2, 3

NOTES:

1. Miscellaneous signals include all signals that are not PCI, GigE, XScale, or SDRAM signals.
2. As required by the *PCI-X Addendum to the PCI Local Bus Specification, Revision 1.0a*.
3. Not tested.
4. I/O Power Supply
5. $V_{CC12min.} = 1.08\text{V}$, $V_{CC33min} = 3.0\text{V}$.

4.4 Targeted AC Specifications

The following section details the AC specifications for GW80314 signal interfaces.

4.4.1 PCI/X Clock Signal Timings

Table 31. PCI/X Clock Timings

Symbol	Parameter	PCI-X		PCI		Units	Notes
		Min.	Max	Min.	Max		
T _{F1}	PCI clock Frequency	50	133	25	66	MHz	1,2
T _{C1}	PCI clock Cycle Time	7.5	20	15	40	ns	1,3
T _{CH1}	PCI clock High Time	3	-	6	-	ns	
T _{CL1}	PCI clock Low Time	3	-	6	-	ns	
T _{SR1}	PCI clock Slew Rate	1	6	1	6	V/ns	4
Spread Spectrum Requirements							
f _{MOD}	PCI clock modulation frequency	30	33	30	33	kHz	
f _{spread}	PCI clock frequency spread	-1	0	-1	0	%	

NOTES:

1. The clock frequency may not change beyond the spread-spectrum limits except while SFN_RST# is asserted.
2. The PCI output clock is limited to SFN_CLK, SFN_CLK/2, SFN_CLK/4.
3. The minimum clock period must not be violated for any single clock cycle, i.e., accounting for all system jitter.
4. This slew rate must be met across the minimum peak-to-peak portion of the clock waveform.

Table 32. DDR SDRAM Clock Timings

Symbol	Parameter	PC 266		Units
		Min.	Max	
T _{F2}	DDR SDRAM clock Frequency	66	100	MHz
T _{C2}	DDR SDRAM clock Cycle Time	10	-	ns
T _{CH2}	DDR SDRAM clock High Time	4.5	5.5	ns
T _{CL2}	DDR SDRAM clock Low Time	4.5	5.5	ns
T _{CS2}	DDR SDRAM clock Period Stability	-	+/-90	ps
T _{skew2}	DDR SDRAM clock skew for SD_CLK[2:0] and SD_CLK#[3:0]	-	240	ps

Table 33. Intel® XScale™ Microprocessor Clock Timings

Symbol	Parameter	XS 100		XS 75		Units
		Minimum	Maximum	Minimum	Maximum	
T _{F3}	Intel® XScale™ microprocessor clock Frequency	-	100	-	75	MHz
T _{C3}	Intel® XScale™ microprocessor clock Cycle Time	10	-	13	-	ns
T _{CH3}	Intel® XScale™ microprocessor clock High Time	3	-	5	-	ns
T _{CL3}	Intel® XScale™ microprocessor clock Low Time	3	-	5	-	ns
T _{CS3}	Intel® XScale™ microprocessor clock Period Stability	-	+/-175	-	+/-175	ps

4.4.2 Dual-Gigabit Ethernet (GigE) Interface Signal Timings

Table 34. AC Specifications for MII Management Interface

Symbol	Parameter	Condition	Min	Max	Units
T _{PERMDC}	Period of MDC MII Management CLock Output	-	60		ns
T _{PWMDC}	Pulse width of MDC Output	-	16		ns
T _{PDMDIO}	Propagation delay of MDIO output from rising edge of MDC	-		7.5	ns
T _{SUMDIO}	Input Setup Time of MDIO to rising edge of MDC	-	4		ns
T _{HMDIO}	Input Hold Time of MDIO after rising edge of MDC	-	3		ns

NOTE: MDC MII Management Interface Clock period is equal to one of the following: SFN_CLK/8, SFN_CLK/16, SFN_CLK/28, SFN_CLK/40, SFN_CLK/56.

Table 35 lists the AC specifications for the G/MII and TBI interface of the dual GigE Controller. For propagation delays, the AC loads are assumed to be transmission lines, so numbers quoted in the specifications assume driving a 50 Ohm load connected to a voltage source = $V_{CCIO}/2$.

Table 35. AC Specifications for G/MII and TBI Interface

Symbol	Parameter	Condition	Min	Max	Units
T _{CTXCLK}	Period of E[x]_TXCLK inputs	10Mb/s mode	399.98	400.02	ns
		100Mb/s mode	39.998	40.002	ns
T _{CGTXCLK}	Period of GTX_CLK input	1000Mb/s mode	7.9992	8.0008	ns
T _{PWTXCLK}	Pulse width of E[x]_TXCLK inputs	10Mb/s mode	180	220	ns
		100Mb/s mode	18	22	ns
T _{PWGTXCLK}	Pulse width of GTX_CLK input	1000Mb/s mode	3.2	4.8	ns
T _{CRXCLK}	Period of E[x]_RXCLK inputs	10Mb/s mode	399.98	400.02	ns
		100Mb/s mode	39.998	40.002	ns
		1000Mb/s mode	7.9992	8.0008	ns
T _{CPMARCLK}	Period of PMA_CLK[x] input	1000Mb/s mode	15.9984	16.0016	ns
T _{PWRXCLK}	Pulse width of E[x]_RXCLK input	10Mb/s mode	180	220	ns
		100Mb/s mode	18	22	ns
		1000Mb/s mode	3.2	4.8	ns
T _{PWPMARCLK}	Pulse width of PMA_CLK[x] input	1000Mb/s mode	6.4	9.6	ns
T _{SKPMA}	Skew between PMA_CLK[x] inputs	1000Mb/s mode	7.5	8.5	ns
T _{PDTX}	Propagation delay of E[x]_TCG after rising edge of E[x]_TXCLK	10Mb/s or 100Mb/s mode	-	12	ns
T _{PDGTX}	Propagation delay of E[x]_TXG after rising edge of GTX_CLK	1000Mb/s mode	-	5	ns
T _{SURX}	Setup time for E[x]_RCG to rising edge of E[x]_RXCLK	10,100,1000Mb/s modes	2		ns
T _{HRX}	Hold time for E[x]_RCG to rising edge of E[x]_RXCLK	G/MII modes	0		ns
T _{SURXTBI}	Setup time for E[x]_RCG to PMA_CLK[x]	TBI mode	2.5		ns
T _{HRXTBI}	Hold time for E[x]_RCG after PMA_CLK[x]	TBI mode	0.5		ns

NOTES:

1. All parameters are valid for both ports of GigE interface (i.e., E[x] = E0 or E1).

4.4.3 PCI/X Interface Signal Timings

Table 36. AC Specifications for PCI/X Interface

Symbol	Parameter	PCI-X 133		PCI-X 66		PCI 66		PCI 33		Units	Notes
		Min.	Max	Min.	Max	Min.	Max	Min.	Max		
T _{OV1}	Clock to Output Valid Delay for bused signals	0.7	3.8	0.7	3.8	1	6	2	11	ns	1,2,3
T _{OV2}	Clock to Output Valid Delay for point to point signals	0.7	3.8	0.7	3.8	2	6	2	12	ns	1,2,3
T _{OF}	Clock to Output Float Delay	-	7	-	7	-	14	-	28	ns	1,7
T _{IS1}	Input Setup to clock for bused signals	1.2	-	1.7	-	3	-	7	-	ns	3,4,8
T _{IS2}	Input Setup to clock for point to point signals	1.2	-	1.7	-	5	-	10,12	-	ns	3,4
T _{IH1}	Input Hold time from clock	0.5	-	0.5	-	0	-	0	-	ns	4
T _{RST}	Reset Active Time	1	-	1	-	1	-	1	-	ms	
T _{RF}	Reset Active to output float delay	-	40	-	40	-	40	-	40	ns	5,6
T _{IS3}	P[x]_REQ64# to Reset setup time	10	-	10	-	10	-	10	-	clocks	
T _{IH2}	Reset to P[x]_REQ64# hold time	0	50	0	50	0	50	0	50	ns	
T _{IS4}	PCI-X initialization pattern to Reset setup time	10	-	10	-	-	-	-	-	clocks	
T _{IH3}	Reset to PCI-X initialization pattern hold time	0	50	0	50	-	-	-	-	ns	

NOTES:

1. See the timing measurement conditions in [Figure 7](#).
2. See [Figure 12](#), [Figure 13](#) and [Figure 14](#).
3. Setup time for point-to-point signals applies to P[x]_REQ# and P[x]_GNT# only. All other signals are bused.
4. See the timing measurement conditions in [Figure 6](#).
5. SFN_RST# is asserted and deasserted asynchronously with respect to SFN_CLK.
6. All output drivers must be floated when SFN_RST# is active.
7. For purposes of Active/Float timing measurements, the HI-Z or "off" state is defined to be when the total current delivered through the component pin is less than or equal to the leakage current specification.
8. Setup time applies only when the device is not driving the pin. Devices cannot drive and receive signals at the same time.

4.4.4 DDR SDRAM Interface Signal Timings

Table 37. AC Specifications for DDR SDRAM Interface

Symbol	Parameter	Min.	Max	Units	Notes
T _{VB1}	SD_DQS output valid time before SD_CLK	-	0.9	ns	1
T _{VA1}	SD_DQS output valid time after SD_CLK	-	0.9	ns	1
T _{VB2}	Address and Control write output valid before SD_CLK	3.9	-	ns	1
T _{VA2}	Address and Control write output valid after SD_CLK	4.3	-	ns	1
T _{VB3}	SD_DQS read input valid time before SD_DQ	-	0.9	ns	2
T _{VA3}	SD_DQS read input valid time after SD_DQ	-	0.9	ns	2
T _{VB4}	SD_DQS write input valid time before SD_DQ	1.7	-	ns	1
T _{VA4}	SD_DQS write input valid time after SD_DQ	1.7	-	ns	1

NOTES:

1. See Figure 9.
2. See Figure 10.

4.4.5 Intel® XScale™ Microprocessor Interface Signal Timings

Table 38. AC Specifications for Intel® XScale™ Microprocessor Interface

Symbol	Parameter	Min.	Max	Units	Notes
T _{OV1}	Output Valid Delay from XS_CLK - XS_DQ[63:0] and XS_BE[7:0]	3.2	8.5	ns	1,3
T _{OV2}	Output Valid Delay from XS_CLK - XS_DVALID and XS_ABORT	3.2	8.5	ns	1,3
T _{IS1}	Input Setup to XS_CLK - XS_DQ[63:0] and XS_BE[7:0]	0.5	-	ns	2
T _{IH1}	Input Hold from XS_CLK - XS_DQ[63:0],XS_BE[7:0]	0.6	-	ns	2
T _{IS2}	Input Setup to XS_CLK - XS_A[15:0], XS_LEN[2:0]	0.5	-	ns	2
T _{IH2}	Input Hold from XS_CLK - XS_A[15:0],XS_LEN[2:0]	0.6	-	ns	2

NOTES:

1. See Figure 7.
2. See Figure 6.
3. These output valid times are specified with 30 pF loading.

4.4.6 UART Interface Signal Timings

Table 39. AC Specifications for UART Interface

Symbol	Parameter	Minimum	Max	Units	Notes
T _{HDSR}	U[x]_DSR# Hold Time	0	-	ns	
T _{SDSR}	U[x]_DSR# Setup Time	60	-	ns	
T _{DRDSR}	U[x]_RTS# - U[x]_DSR# Delay Time	30	-	ns	
T _{DWDSR}	U[x]_CTS# - U[x]_DSR# Delay Time	30	-	ns	
T _{HRX}	U[x]_RX Hold Time	30	-	ns	
T _{SRX}	U[x]_RX Setup Time	30	-	ns	
T _{DTX}	U[x]_TX Transmit Cycle Delay Time	125	-	ns	
T _{HRTS}	U[x]_DSR# - U[x]_RTS# Hold Time	20	-	ns	
T _{DRTS}	U[x]_RTS# - U[x]_TX Data Delay Time	-	60	ns	1
T _{DFRTS}	U[x]_RTS# - U[x]_TX Floating Data Delay Time	-	100	ns	1
T _{DRX}	U[x]_RX Receive Cycle Delay Time	150	-	ns	
T _{HCTS}	U[x]_DSR# - U[x]_CTS# Hold Time	20	-	ns	

NOTES:

1. Output has external load of 100pF. Charge and discharge times determined by V_{OL}, V_{OH}, and external load.

4.4.7 Peripheral Bus Interface (PBI) Signal Timings

Table 40. AC Specifications for PBI Interface

Symbol	Parameter	Min.	Max	Units	Notes
T _{DPAD}	SFN_CLK - PBI_AD[31:0] Delay Time	-	10	ns	
T _{SPAD}	PBI_AD[31:0] Setup Time	0	-	ns	
T _{HPAD}	PBI_AD[31:0] Hold Time	5	-	ns	
T _{DPCS}	SFN_CLK - PBI_CS#[3:0] Delay Time	-	10	ns	
T _{DPLE}	SF_CLK - PBI_LE Delay Time	-	10	ns	
T _{DPRW}	SF_CLK - PBI_RW Delay Time	-	10	ns	

4.4.8 I²C Interface Signal Timings

Table 41 lists the AC specifications for GW80314 I²C interfaces. The specifications are valid for both the GPIO I²C interface and the I²C interface contained within the DDR SDRAM controller.

Table 41. AC Specifications for I²C Interface

Symbol	Parameter	Std. Mode		Units	Notes
		Min.	Max		
F _{SCL}	SD_I2C_CLK/I2C_SCLK Clock Frequency	0	100	KHz	
T _{BUF}	Bus Free Time Between STOP and START Condition	4.7	-	μs	1
T _{HDSTA}	Hold Time (repeated) START condition	4	-	μs	1,3
T _{LOW}	SD_I2C_CLK/I2C_SCLK Clock Low Time	4.7	-	μs	1,2
T _{HIGH}	SD_I2C_CLK/I2C_SCLK Clock High Time	4	-	μs	1,2
T _{SUSTA}	Setup Time for a Repeated START condition	4.7	-	μs	1
T _{HDDAT}	Data Hold Time	0	3.45	μs	1
T _{SUDAT}	Data Setup Time	250	-	ns	1
T _{SR}	SD_I2C_CLK, SD_I2C_SDA, I2C_SCLK, and I2C_SDA Rise Time	-	1000	ns	1
T _{SF}	SD_I2C_CLK, SD_I2C_SDA, I2C_SCLK, and I2C_SDA Fall Time	-	300	ns	1
T _{SUSTO}	Setup Time for STOP Condition	4	-	μs	1

NOTES:

1. See Figure 8.
2. Not tested.
3. After this period, the first clock pulse is generated.

4.4.9 Boundary Scan Test Signal Timings

Table 42. Boundary Scan Test Signal Timings

Symbol	Parameter	Min.	Max	Units	Notes
T _{BSF}	TCK Frequency	0	10	MHz	
T _{BSCH}	TCK High Time	50	-	ns	Measured at 1.5V, 1
T _{BSCl}	TCK Low Time	50	-	ns	Measured at 1.5V, 1
T _{BSCR}	TCK Rise Time	-	25	ns	0.8V to 2.0V, 1
T _{BSCF}	TCK Fall Time	-	25	ns	2.0V to 0.8V, 1
T _{SIS1}	Input Setup to TCK	10	-	ns	4
T _{BSIH1}	Input Hold from TCK	10	-	ns	4
T _{BSOV1}	TDO Output Valid Delay from falling edge of TCK.	-	15	ns	2, 3
T _{OF1}	TDO Output Float Delay from falling edge of TCK	-	15	ns	2, 5

NOTES:

1. Not tested.
2. Outputs precharged to V_{CC5}.
3. See [Figure 7](#).
4. See [Figure 6](#).
5. A float condition occurs when the output current becomes less than I_{LO}. Float delay is not tested. See [Figure 7](#).



4.5 AC Timing Waveforms

Figure 6. Input Timing Measurement Waveforms

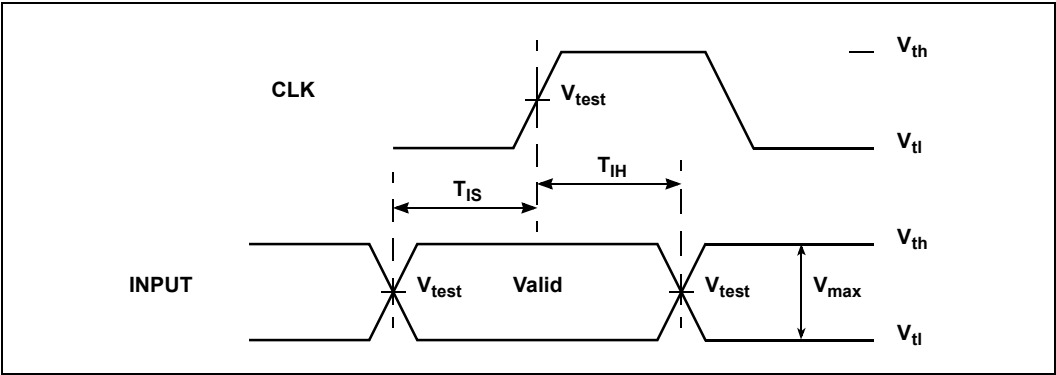


Figure 7. Output Timing Measurement Waveforms

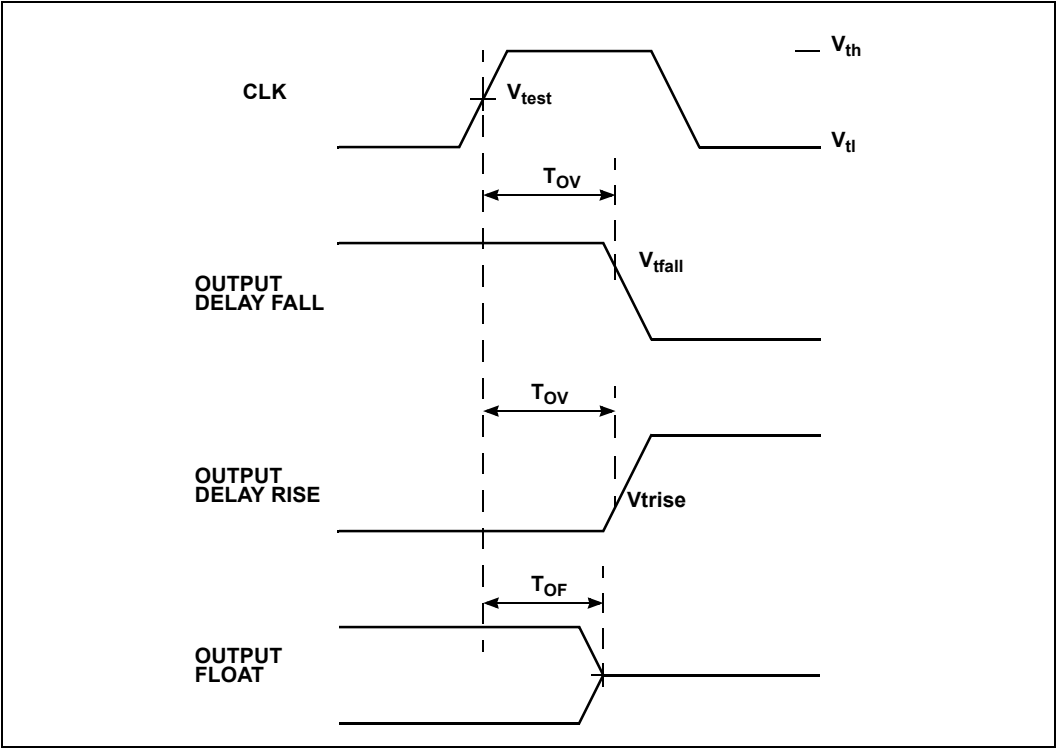


Figure 8. I²C Interface Signal Timings

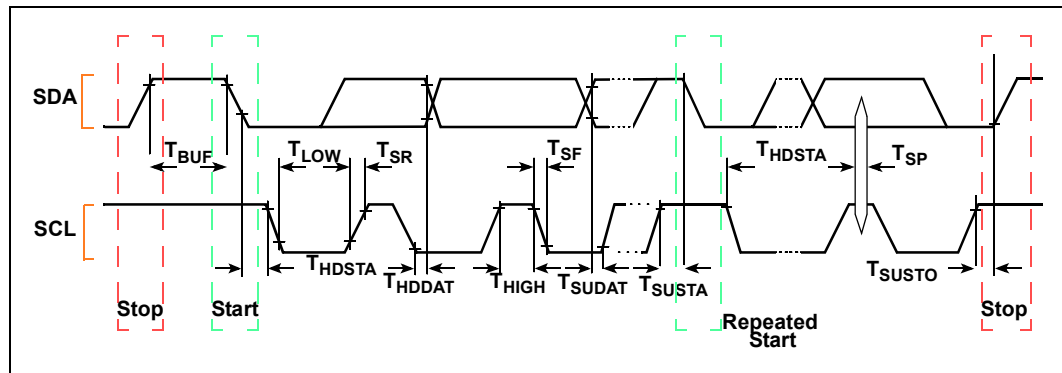


Figure 9. DDR SDRAM Write Timings

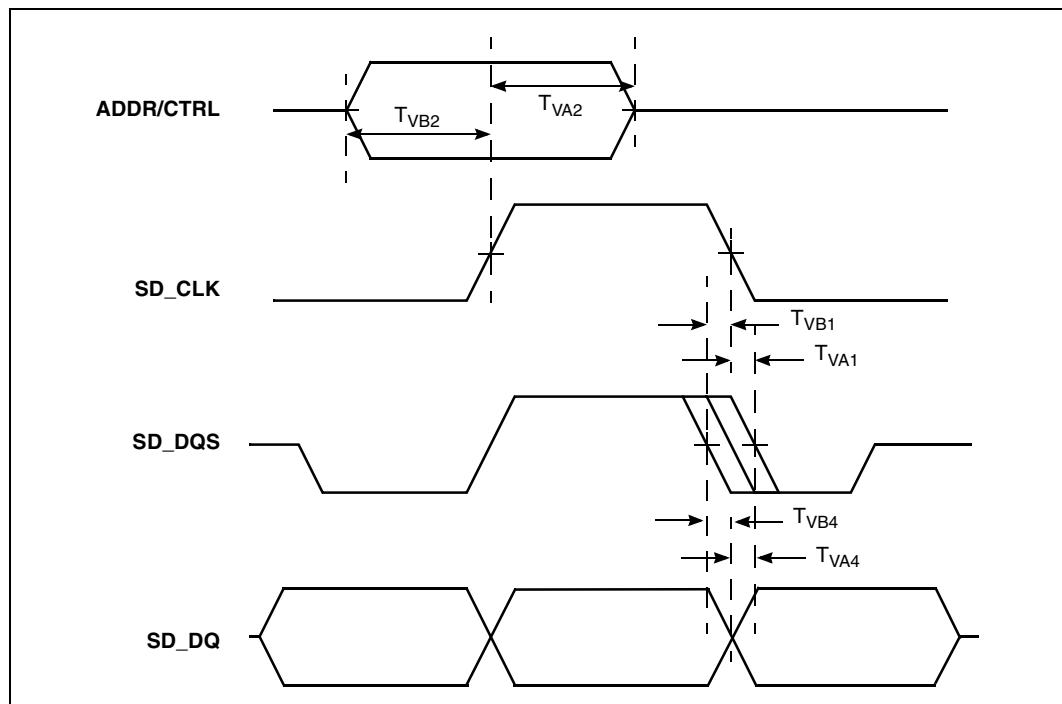
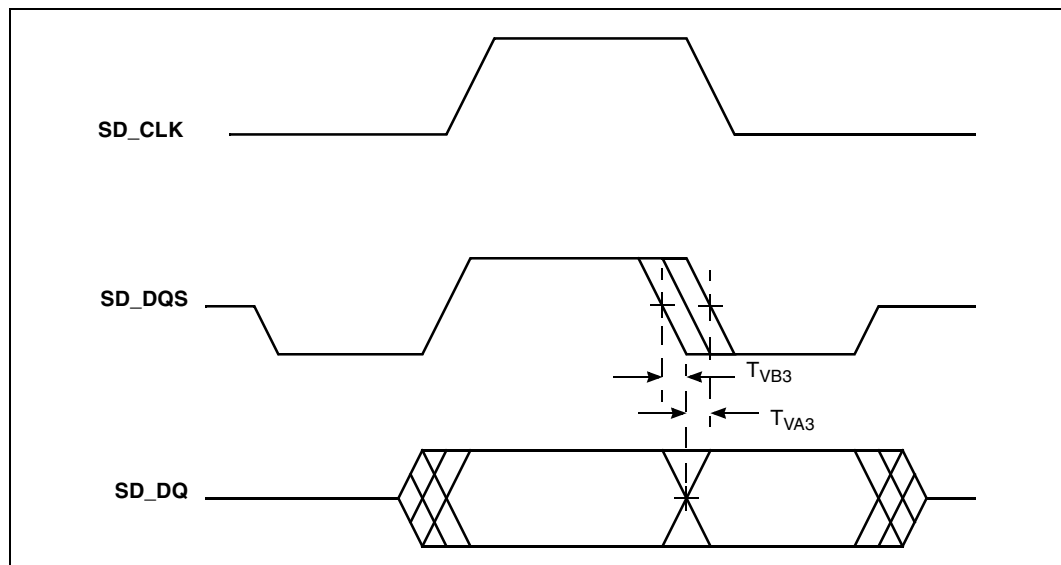


Figure 10. DDR SDRAM Read Timings



4.6 AC Test Conditions

Table 43 and Figure 11 through Figure 14 summarize the AC test and measurement conditions to be used for the GW80314.

Table 43. AC Measurement Conditions

Symbol	PCI-X	PCI	DDR	Intel® XScale™ Microprocessor	GigE	Units	Notes
V_{tch}	$0.6 \cdot V_{CC33}$	$0.6 \cdot V_{CC33}$	-	$0.6 \cdot V_{CC33}$	$0.6 \cdot V_{CC33}$	V	
V_{tcl}	$0.2 \cdot V_{CC33}$	$0.2 \cdot V_{CC33}$	-	$0.2 \cdot V_{CC33}$	$0.2 \cdot V_{CC33}$	V	
V_{th}	$0.6 \cdot V_{CC33}$	$0.6 \cdot V_{CC33}$	2.0	$0.6 \cdot V_{CC33}$	$0.6 \cdot V_{CC33}$	V	
V_{tl}	$0.25 \cdot V_{CC33}$	$0.2 \cdot V_{CC33}$	0.5	$0.2 \cdot V_{CC33}$	$0.2 \cdot V_{CC33}$	V	
V_{test}	$0.4 \cdot V_{CC33}$	$0.4 \cdot V_{CC33}$	1.25	$0.4 \cdot V_{CC33}$	$0.4 \cdot V_{CC33}$	V	
V_{trise}	$0.285 \cdot V_{CC33}$	$0.285 \cdot V_{CC33}$	1.25	$0.285 \cdot V_{CC33}$	$0.285 \cdot V_{CC33}$	V	
V_{fall}	$0.615 \cdot V_{CC33}$	$0.615 \cdot V_{CC33}$	1.25	$0.615 \cdot V_{CC33}$	$0.615 \cdot V_{CC33}$	V	
V_{max}	$0.4 \cdot V_{CC33}$	$0.4 \cdot V_{CC33}$	1.5	$0.4 \cdot V_{CC33}$	$0.4 \cdot V_{CC33}$	V	
Slew Rate	1 - 6	1 - 6	1.5	1.5	1.5	V/ns	1

NOTE: Input signal slew rate is measured between V_{IL} and V_{IH} .

Figure 11. AC Test Load for all Signals Except PCI and DDR SDRAM

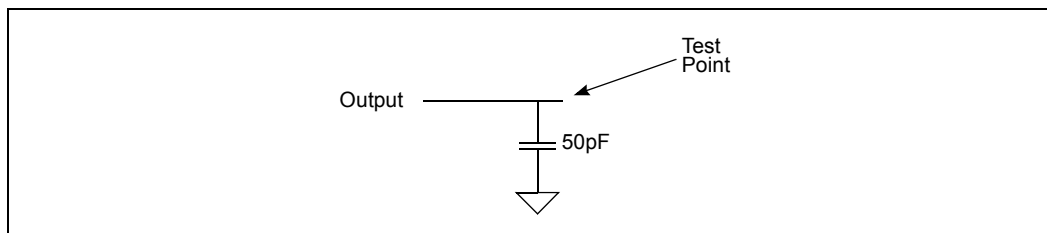


Figure 12. PCI/PCI-X $T_{OV(max)}$ Rising Edge AC Test Load

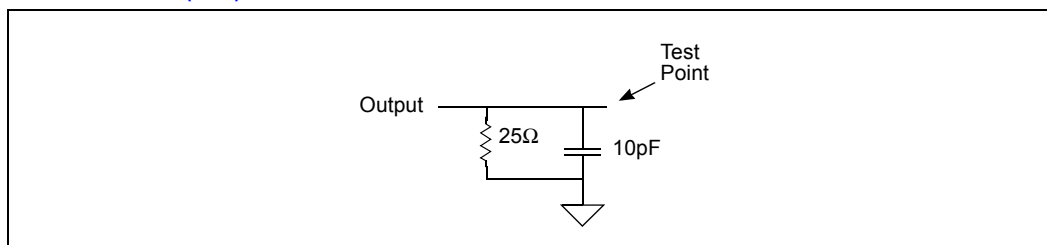


Figure 13. PCI/PCI-X $T_{OV(max)}$ Falling Edge AC Test Load

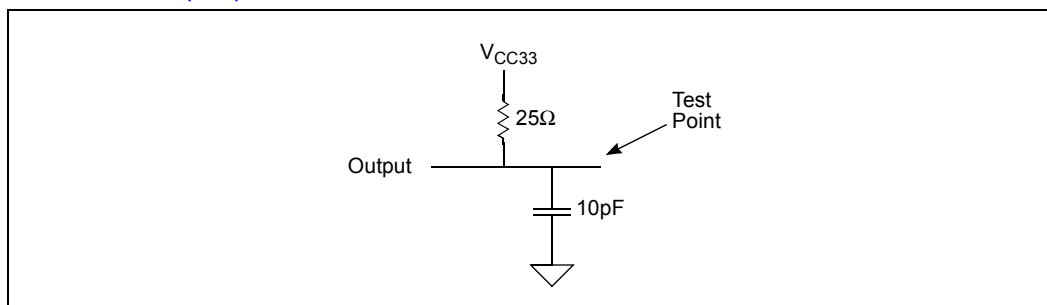
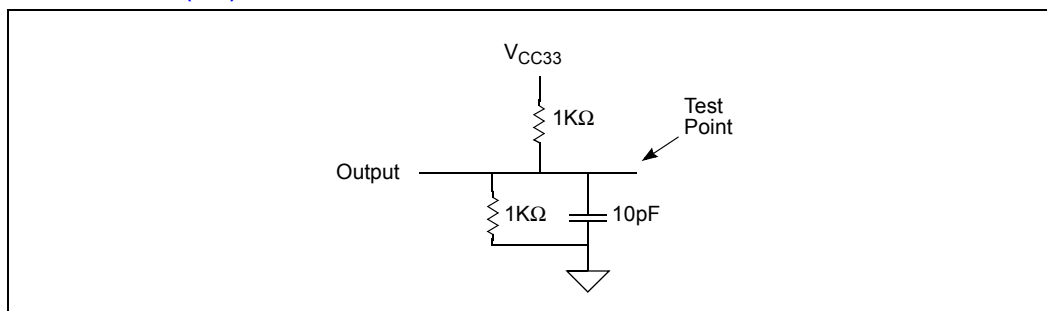


Figure 14. PCI/PCI-X $T_{OV(min)}$ AC Test Load



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